There & Back Again

Full-stack Reverse Engineering of the Original Microsoft Xbox



by markus 'doom' gaasedelen

4000 hours

over about 3 years
2021 → 2024









whoami

- Markus Gaasedelen
 - o doom
- Principal, Security Research
 - Reverse Engineering
 - Software Exploitation
- Co-founder of RET2 Systems
 - o est. 2017









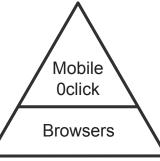
The Layman's Guide to Zero-Day Engineering

Demystifying the exploit development lifecycle

gaasedelen & itszn



Software



Custom Tooling, Fuzzing

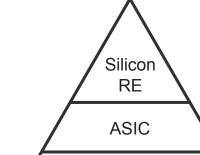
0days

Basic Exploitation, CTF, WarGames

Disassemblers, Debuggers

Software Development, C, Python

Hardware



FPGA, High Speed

KiCad, PCB Design

Basic Fault Injection, Power Analysis

Logic Analyzers, Oscilloscopes

Soldering, Multimeters, UART, Flash Dumps

Software

Mobile Oclick Browsers

0days

Custon Tooling, Fuzzing

Basic Exploration, CTF, WarGames

Disass mblers, Debuggers

Software Levelopment, C, Python

Hardware

Silicon RE

ASIC

FPGA, High Speed

KiCad, PCB Design

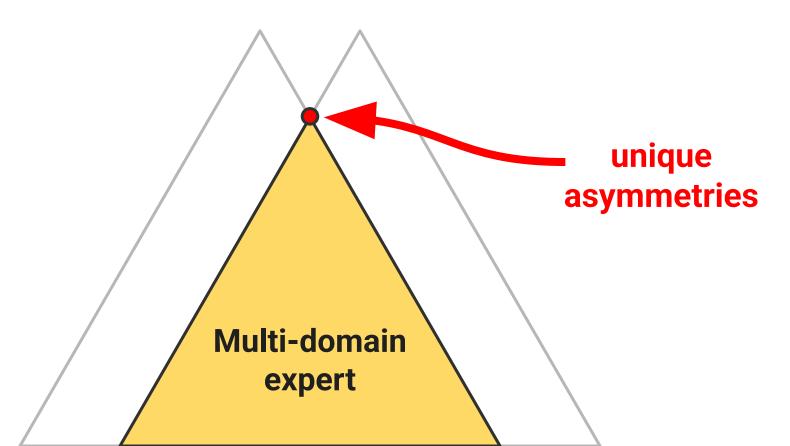
Basic Fault Injection, Power Analysis

Logic Analyzers, Oscilloscopes

Soldering, Multimeters, UART, Flash Dumps

FPGA bitstream fall time. crosstalk capacitor buried via capacitor buried via decapsulation decapsulation decapsulation arduinoboundary scan IDT electrolytic capacitor logic analyzer decapsulation altime arduinoboundary scan IDT electrolytic capacitor logic analyzer logic analyzer clock skew mil clock glitching low-pass filterparasitics bodge divider bodge with the clock glitching low-pass filterparasitics bodge clock glitching low-pass filterparasitics bodge plane LDTO acetone rinses varistors ground plane LDTO acetone rinses varistors of ground plane LDTO acetone rinses varistors of ground plane LDTO acetone rinses varistors with the copper pour bodge by the copper pour bodge divider bodge was ground plane LDTO acetone rinses varistors of ground plane LDTO acetone rinses varistors was grounded by the copper pour bodge by the copper pour bodge was ground by the copper pour bodge was grounded b trimming fault injection differential pair ground stitching thermodynamics dielectric constant shielding op-amp nitric acid fusion 1360 bondwire

SW + HW



Agenda

Prologue

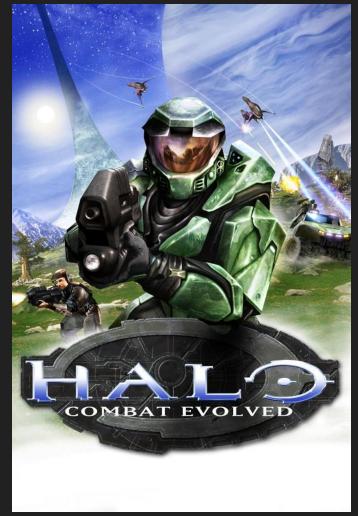
Xbox

- Background & Resources
- Basic Hardware Hacking
- Basic Hardware Engineering
- Bill Gates' Secret Bondwire
- PIC16 / SMC Research
- CPU Interposers

Epilogue



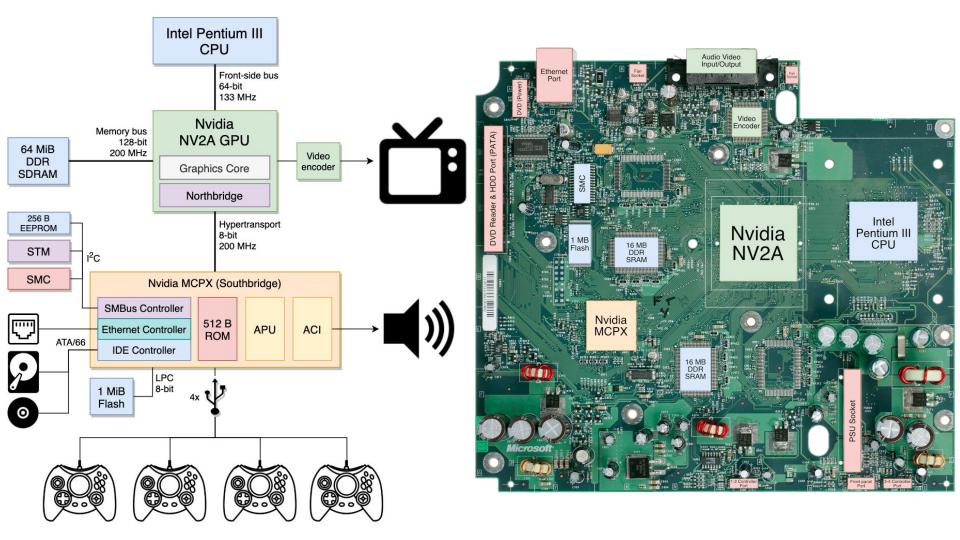
The 'Original' Microsoft Xbox, 2001













Leaked Technical Resources



- Complete Source Tree Leak -- HOLY GRAIL
 - Microsoft.OriginalXbox.Repo.zip April 2002, the '4400' leak (1.2gb)
- Retail Motherboard Schematics
 - Launch, XBLADE, Tuscany (PDFs)
- Xbox Hardware Design Specification
 - v0.91, v1.00, v1.02 (PDFs)
- Official Xbox SDK's used by Game Developers
 - XDK 5849.17 being the 'final' one
- Misc 'confidential' datasheets / design documents ...

```
BUILD: Elapsed time [0:00:13.469]
BUILD: Linking z:\xbox\private\ntos\ke\up directory
BUILD: Elapsed time [0:00:13.813]
BUILD: Linking z:\xbox\private\ntos\net\libx directory
BUILD: Elapsed time [0:00:14.094]
BUILD: Linking z:\xbox\private\ntos\net\libxs directory
BUILD: Elapsed time [0:00:14.359]
BUILD: Linking z:\xbox\private\ntos\init\console directory
Linking Executable - z:\xbox\private\ntos\init\console\ob.j\i386\xboxkrnl.exe for i386
Binplacing - z:\xbox\private\ntos\init\console\obj\i386\xboxrom_dvt4.bin for i386
Binplacing - z:\xbox\private\ntos\init\console\init\console\obj\i386\xboxrom_dvt4.bin for i386
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Binplacing - z:\xbox\private\ntos\init\console\obj\i386\xboxrom_gt.bin for i386
Binplacing - z:\xbox\private\ntos\init\console\obj\i386\xboxkrnl.map for i386
Binplacing - z:\xbox\private\ntos\init\console\init\console\ob.j\i386\xboxkrnl.map for i386
BUILD: Elapsed time [0:00:15.859]
BUILD: Linking z:\xbox\private\ntos\dd\usb\xkbd directory
BUILD: Elapsed time [0:00:15.984]
BUILD: Linking z:\xbox\private\ntos\xapi\k32\lib directory
BUILD: Elapsed time [0:00:16.344]
BUILD: Linking z:\xbox\private\ntos\xapi\dll directory
BUILD: Elapsed time [0:00:16.484]
BUILD: Finish time: Sat Apr 03 08:00:04 2021
BUILD: Done
    1 files compiled
    3 libraries built
    2 executables built - 4 Warnings
[Z:\xbox\private\ntos] _
```

Retail BIOS Timeline

- 3944 September 2001
- 4034 October 2001
- 4817 July 2002
- 5101 October 2002
- 5530 April 2003
- 5713 August 2003
- 5838 December 2003

4400 - April 2002 (Full source leak)

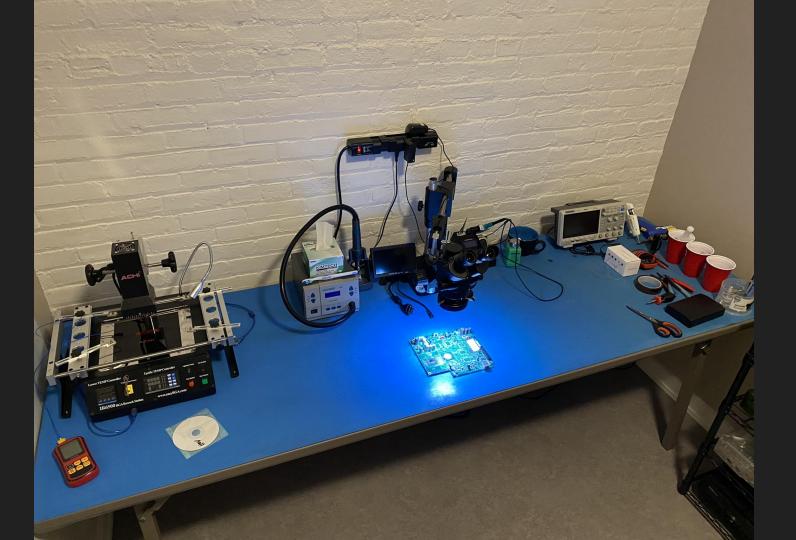
Retail BIOS Breakdown

- Xbox Flash ROM 256kb
 - ~8kb for HW initialization logic ('xcodes')
 - ~24kb for bootloader(s) (bldr32 / preldr32 or '2bl' / 'fbl')
 - ~224kb for encrypted+compressed Kernel & Boot Animation (xboxkrnl.exe)
 - ~600kb decompressed
 - 200kb Kernel, 400kb for the boot animation (DirectX)
 - NT-based, heavily pared down Windows 2000 Kernel

512 byte 'secret' bootrom

- Establishes the 'chain of trust'
- Burned into the MCPX silicon
- First x86 instructions executed out of CPU reset

Basic Hardware Hacking



Recommended Lab Equipment

- Trinocular microscope -- \$500
- Soldering station -- \$125
- Hot air station -- \$150
- Misc tools -- \$125
 - Micro cutter, Tweezers
 - iFixit Mako Driver Kit
 - Grinding pen
 - Multimeter
- Supplies -- \$100
 - Kester solder, leaded 63/37
 - STIRRI-V3-TF flux (syringe)
 - Kimtech wipes, cotton q-tips
 - 99% isopropyl alcohol
 - 3-mil nitrile gloves
 - 30awg wire kit

\$1000 USD

Trinocular microscope, double boom

(Eakins, AmScope, etc)



\$272.54 \$332.36 18% off

Tax excluded, add at checkout if applicable.

up to 4 x \$68.14 with no interest one of Klama.

3.5X 90X 180X Simul-Focus Double Boom Stand Trinocular Stereo Zoom Microscope 48MP 55MP 2K 4K HDMI VGA USB Camera For PCB Repair

+ + + + 4.3 3 Reviews | 24 sold

Color: B HDMI VGA Camera

















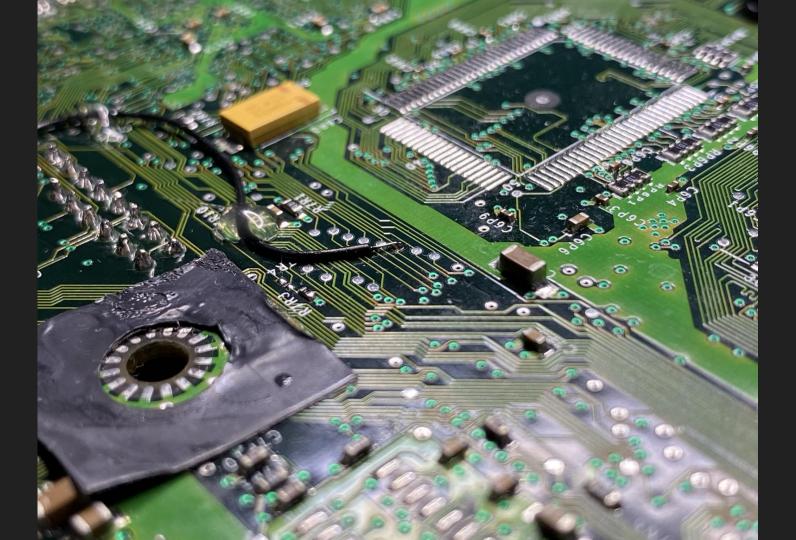








+\$250 shipping







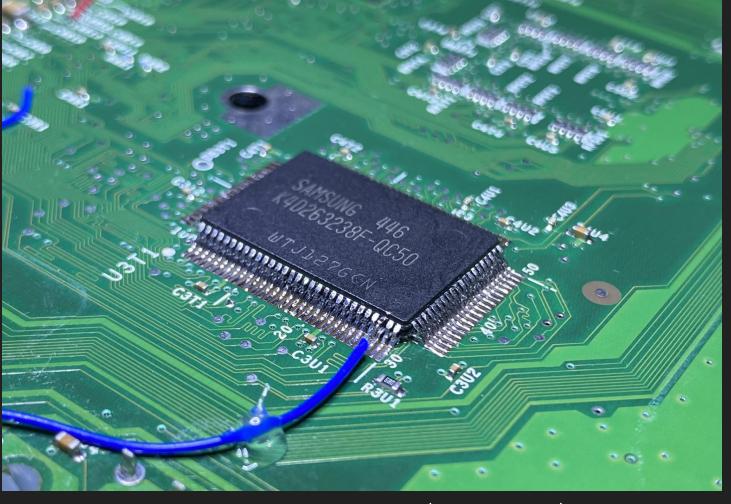


https://github.com/Ryzee119/OpenXenium

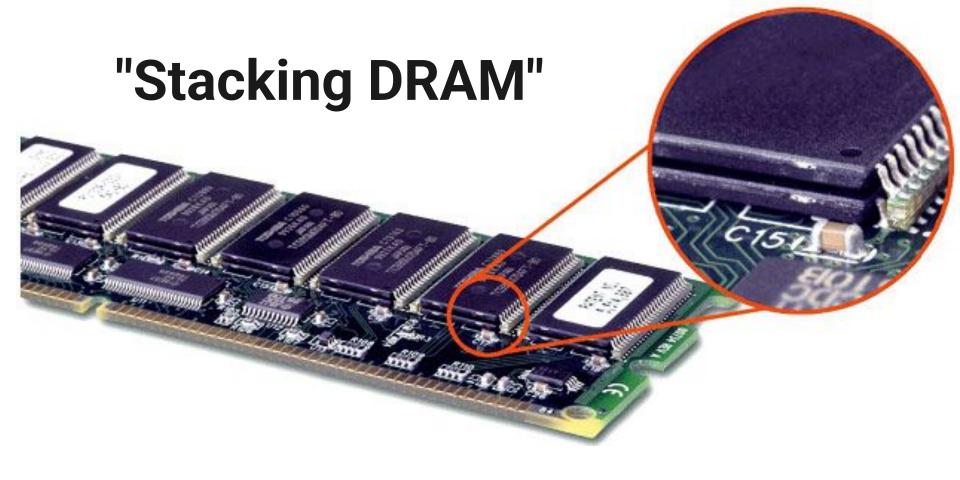




64mb → 128mb RAM upgrade

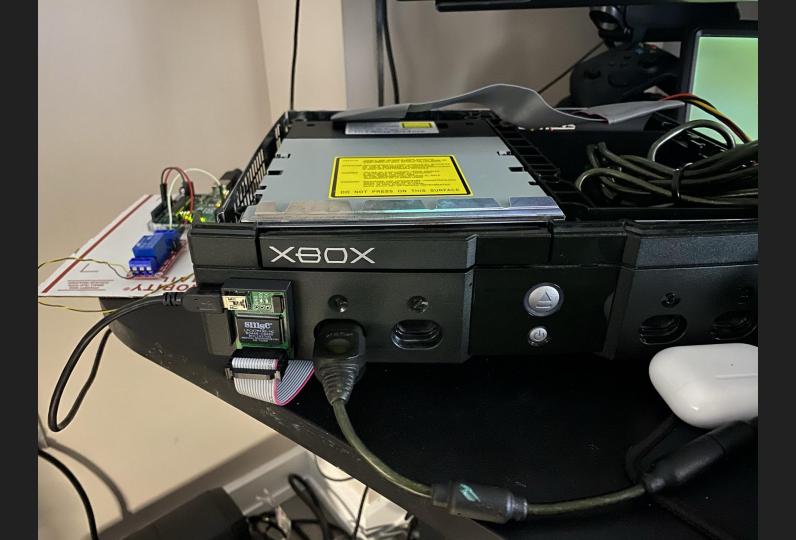


Stacking RAM chips (on rev 1.6)



https://bit-tech.net/reviews/tech/memory/the_secrets_of_pc_memory_part_2/7/

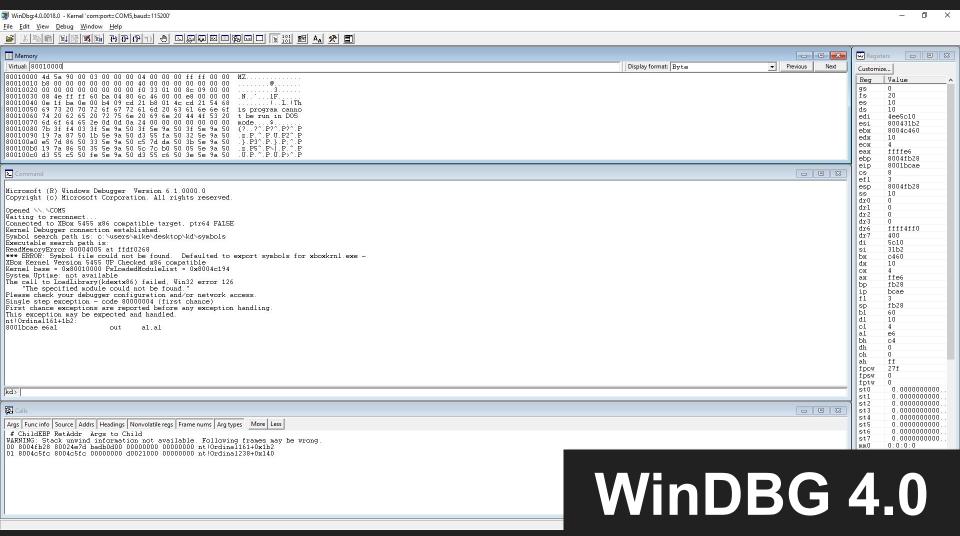
Basic Hardware Engineering

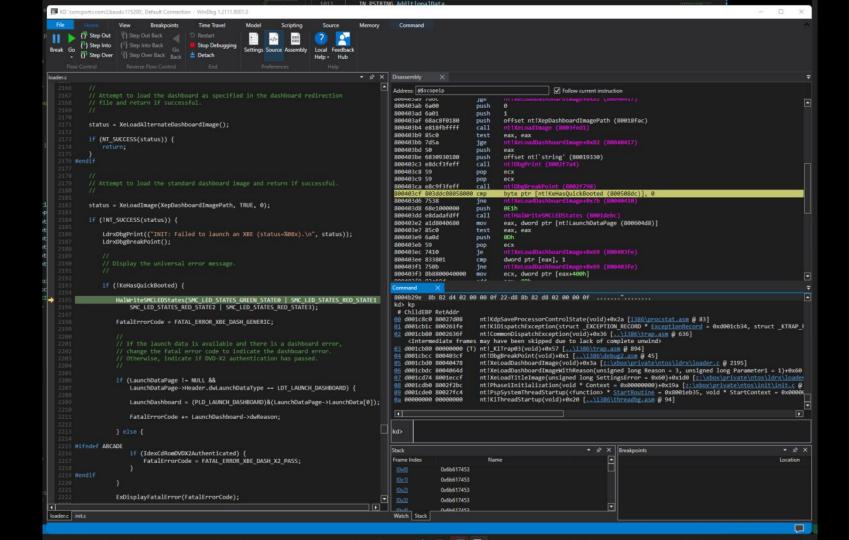


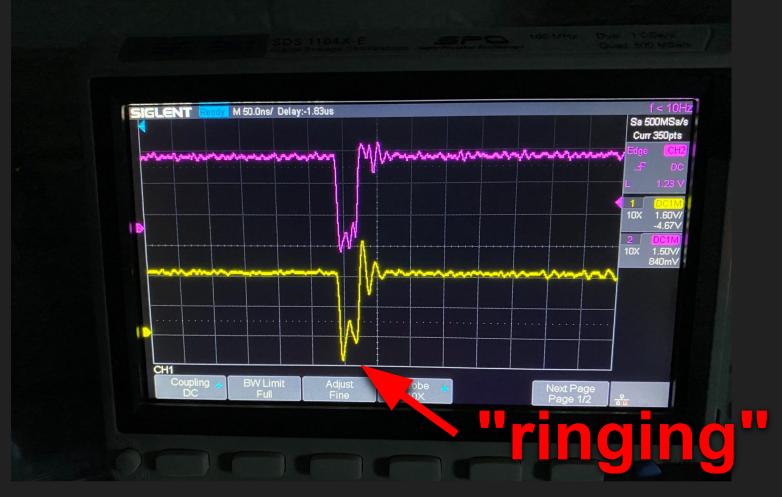


https://github.com/XboxDev/serial-usb-adapter





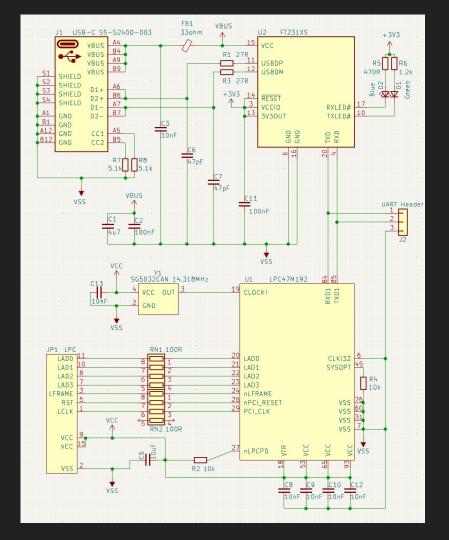


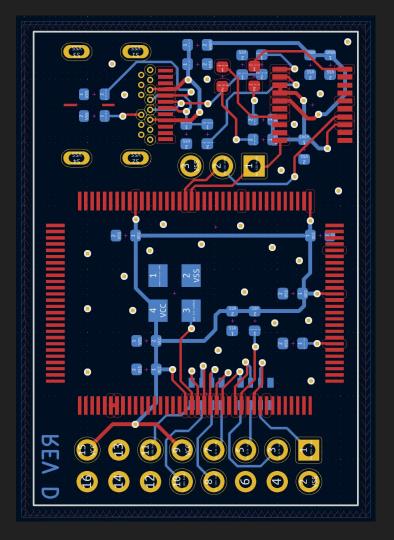


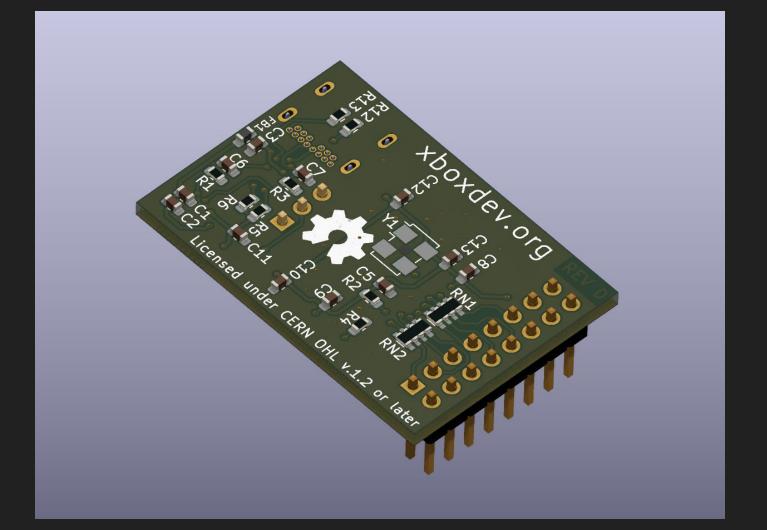
https://github.com/XboxDev/serial-usb-adapter/issues/6

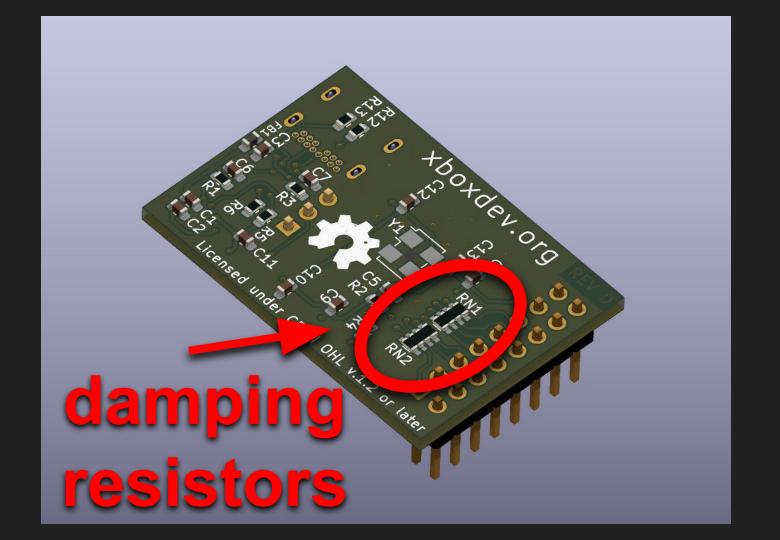
Cac

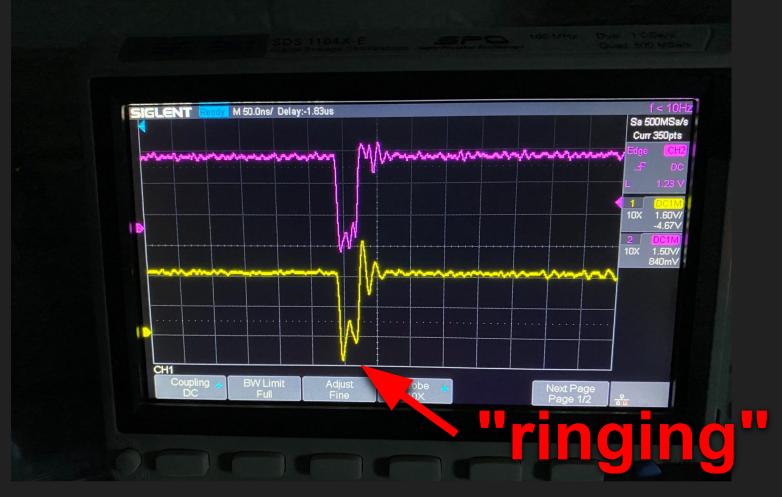
Dimensions Other items







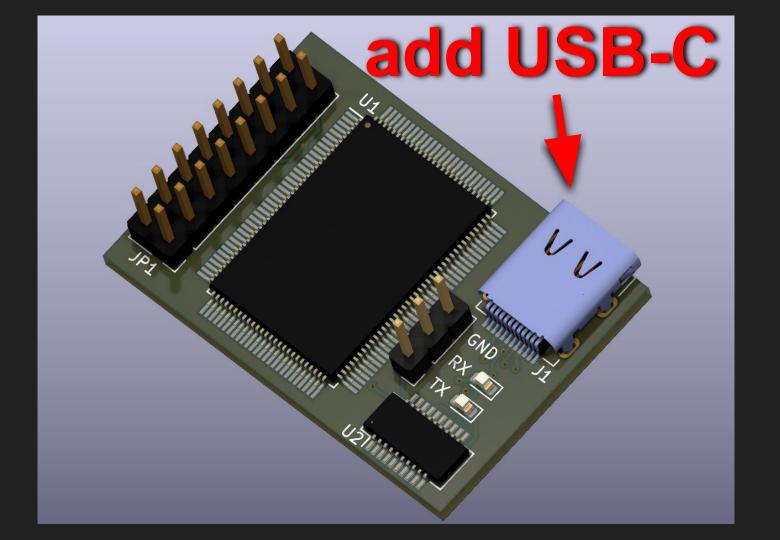


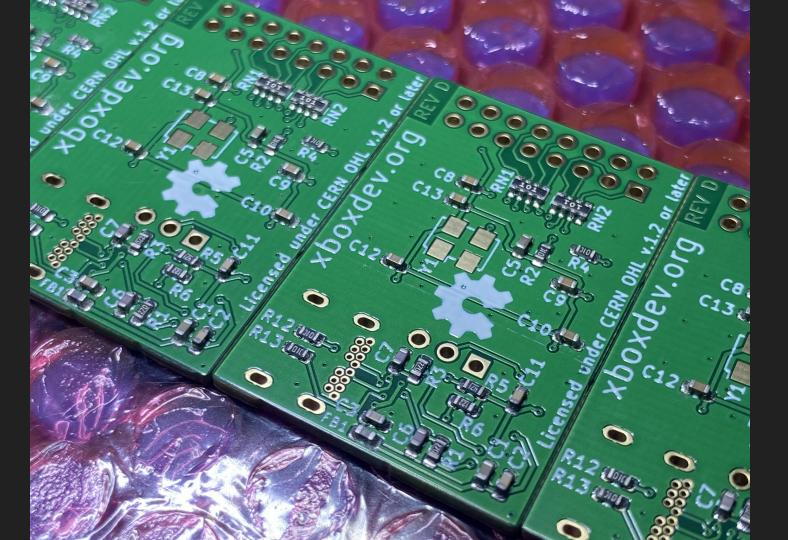


https://github.com/XboxDev/serial-usb-adapter/issues/6



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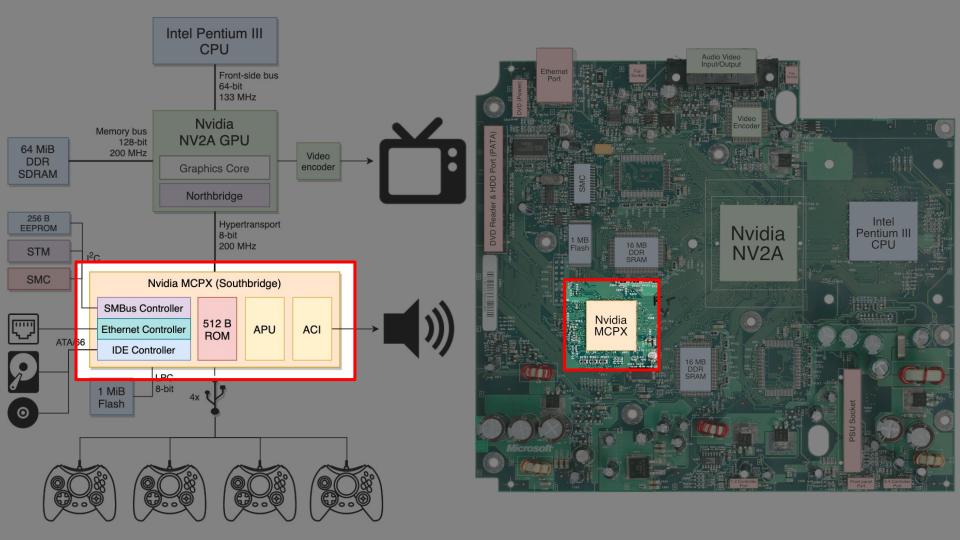




Basic Hardware Engineering

- Modify an existing, open-source KiCad project
 - Schematic Editing
 - PCB Layout Editing
 - Footprint / Symbol Editing
 - Generate Gerber files
- Get PCBs manufactured (JLCPCB)
 - Optionally, purchase partial PCB Assembly services
- Experiment with Oscilloscopes and Logic Analyzers

Bill Gates' Secret Bondwire





NVIDIA MCPX (Southbridge)

"Media Communication Processor"

Handles Peripheral I/O (USB, IDE, Networking, Flash...)

- Contains "secret" retail bootrom (x86) fed to CPU
 - Establishes the chain of trust







MCP-1

Preliminary Confidential Information Version 0.15 – August 2000



MCP-1TM

Media Communication Processor (South Bridge)

PRELIMINARY CONFIDENTIAL INFORMATION

Preliminary Confidential Information Version 0.15 – August 2000

8.0 XMode Operation

XMode is a Microsoft specific feature that can only be enabled via internal bond pads.

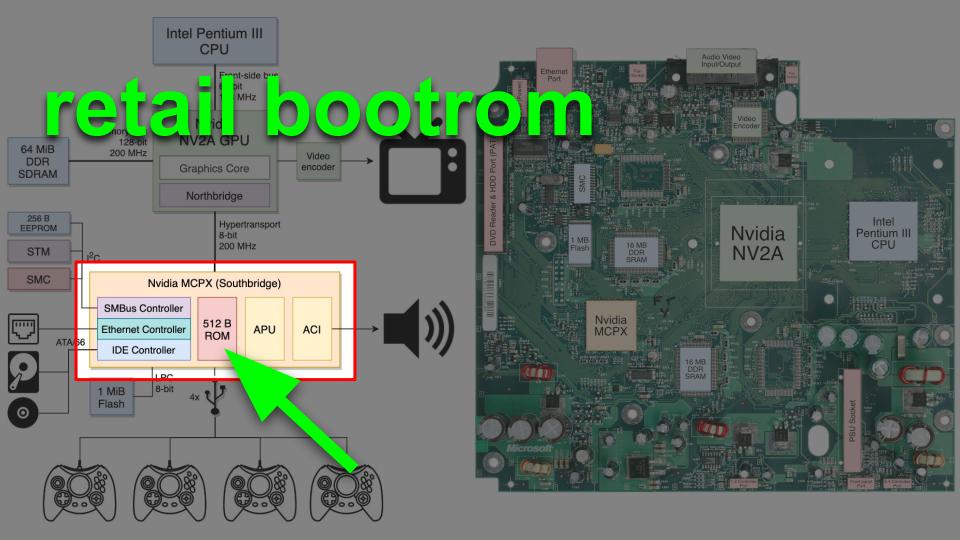
8.1 Bonding Options

MCP1 uses the following Bonding Options:

Pin Strap	Function	Bonded Value
XBox Mode[1:0]	XBox Functionality	00 – PC-Mode
		01 - X-Mode; PCI Bus; Internal ROM Disabled
	XM2	10 - X-Mode; ROM Bus; Internal ROM Disabled;
	XM3	11 – X-Mode; ROM Bus; Internal ROM Enabled;

The bond pads are powered off of the VDD3 ring.

Note: Xbox Mode[0] is available as a pin during the prototyping stage.



Preliminary Confidential Information Version 0.15 – August 2000

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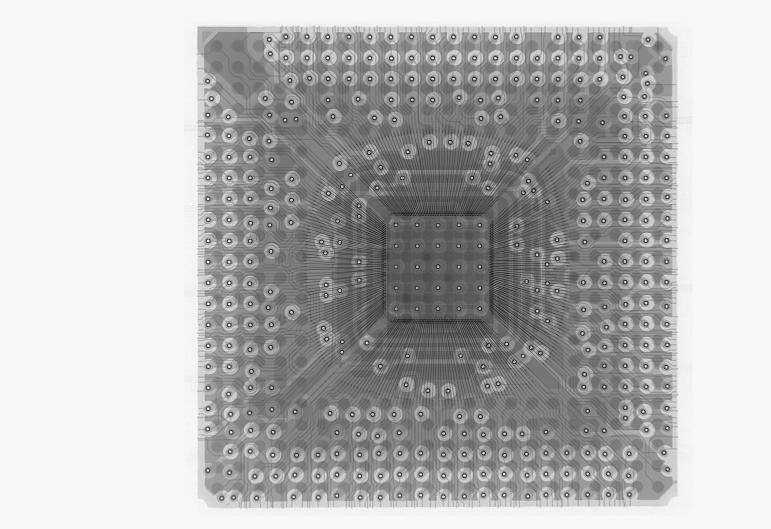
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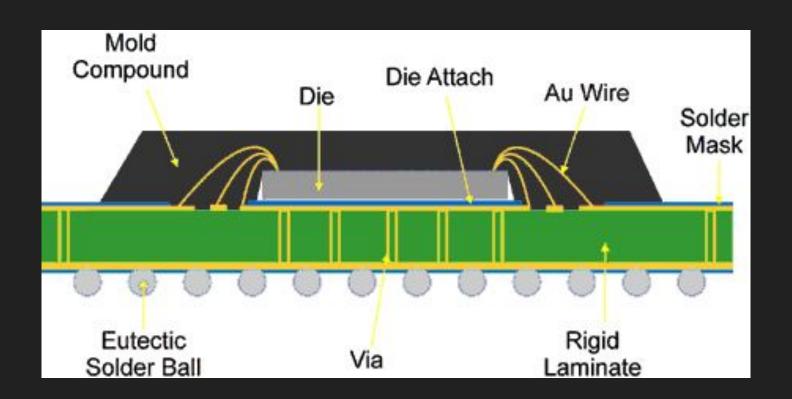
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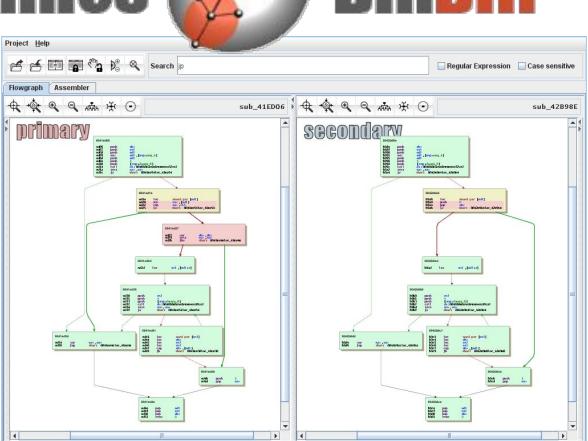






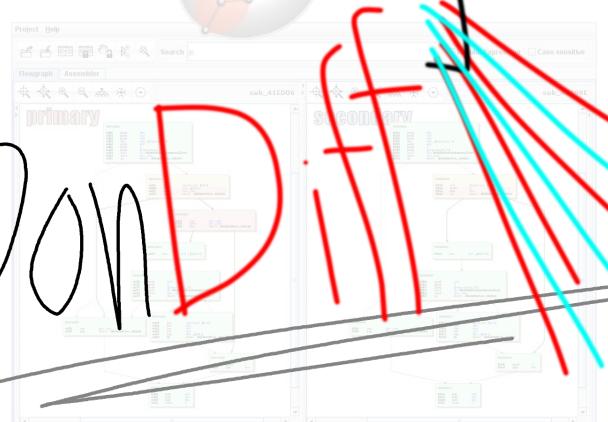


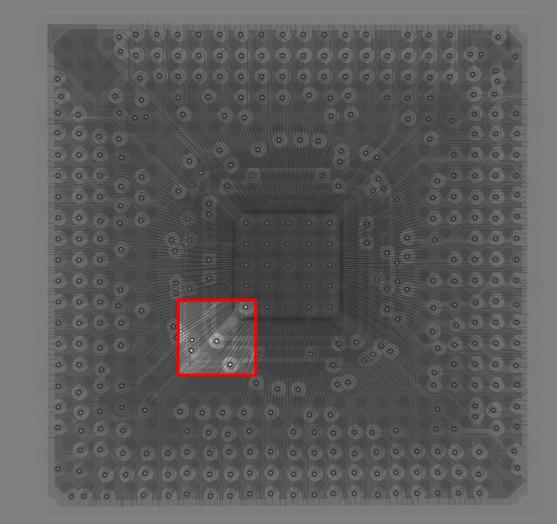
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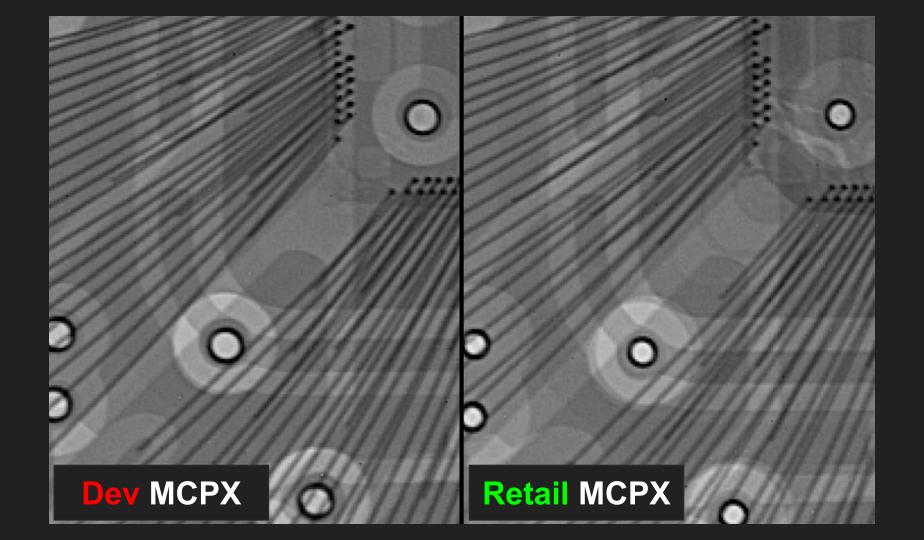


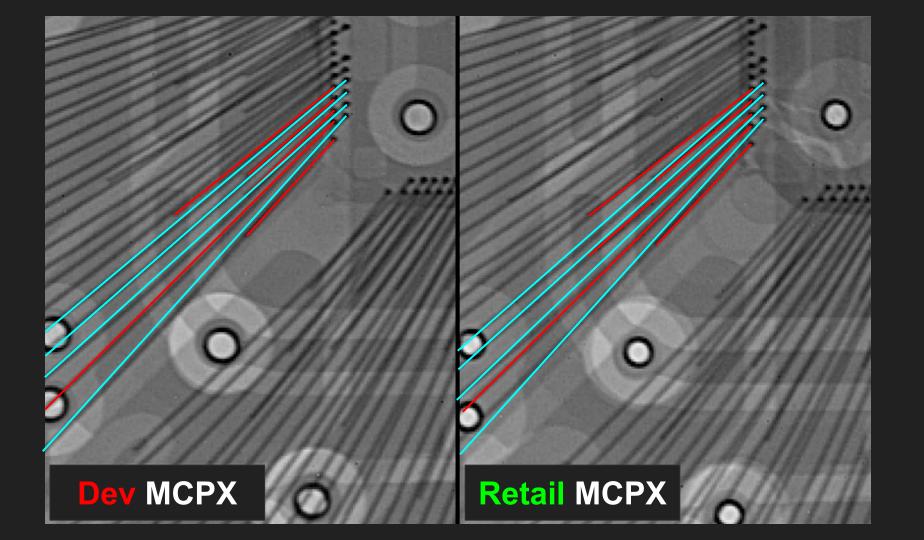
Project Help

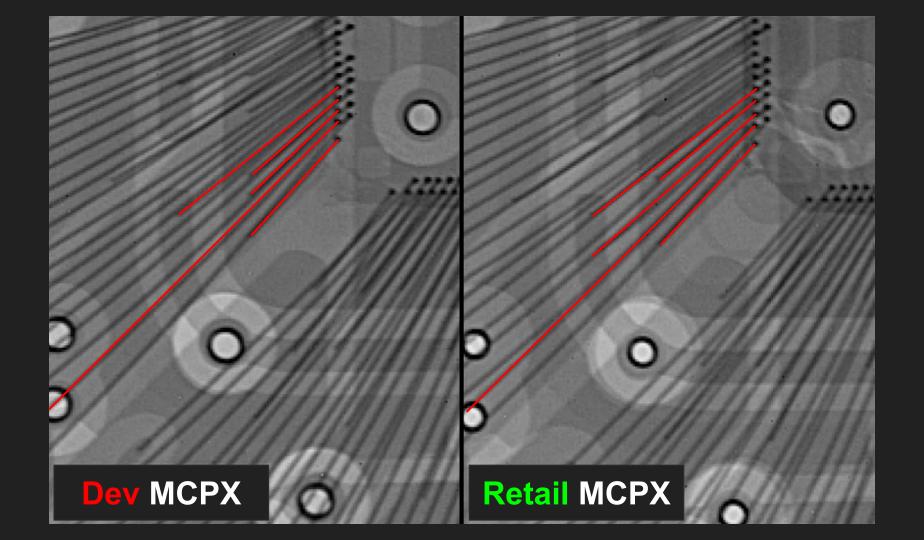
Flowgraph Assembler

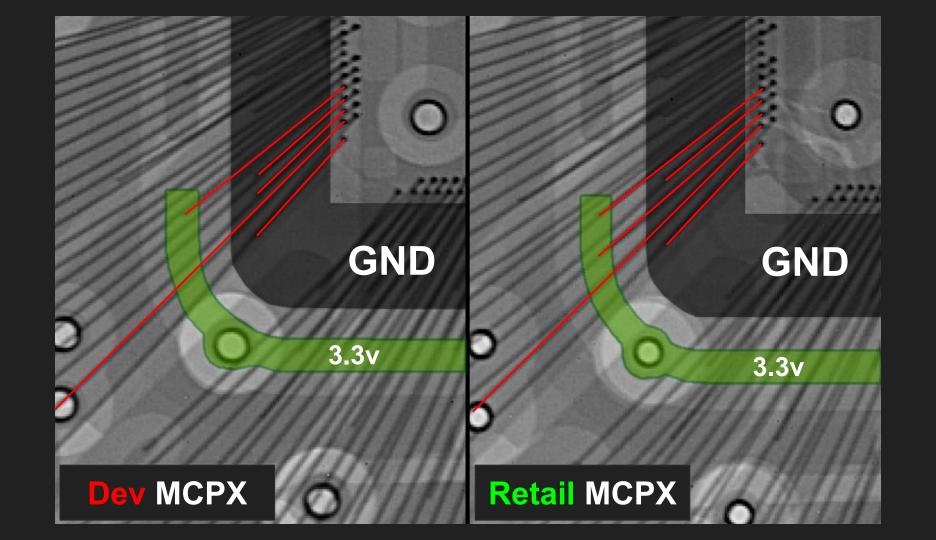


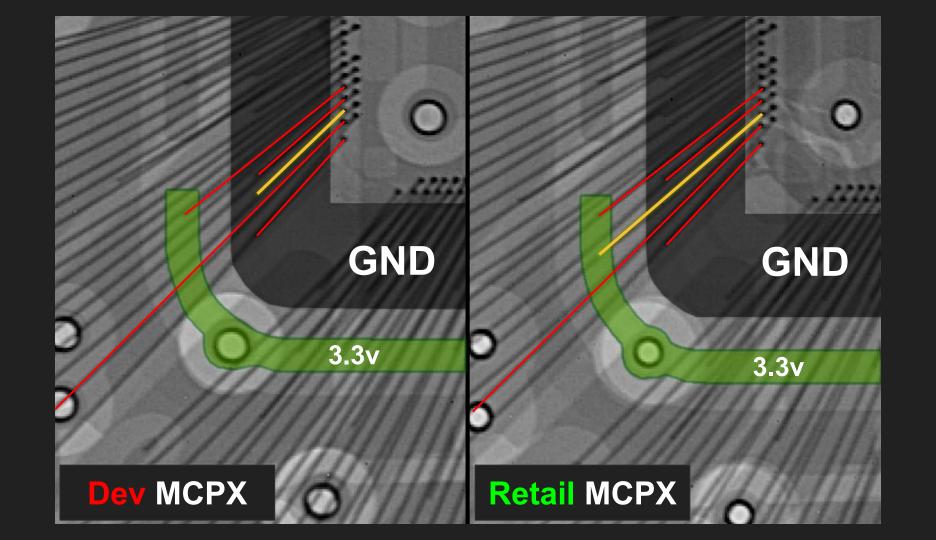




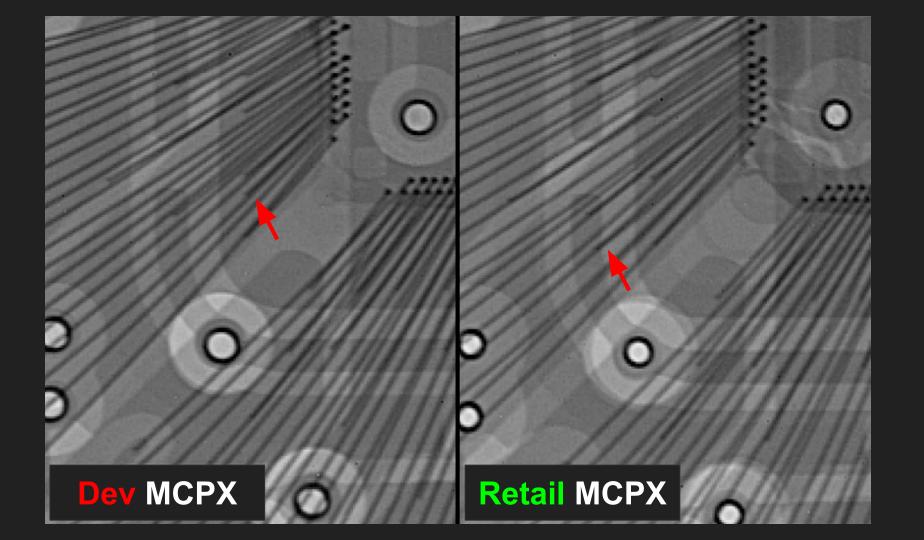




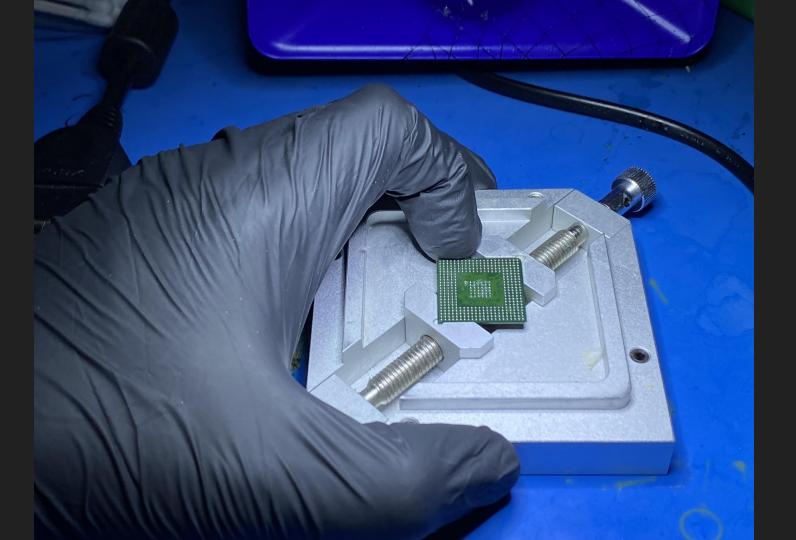




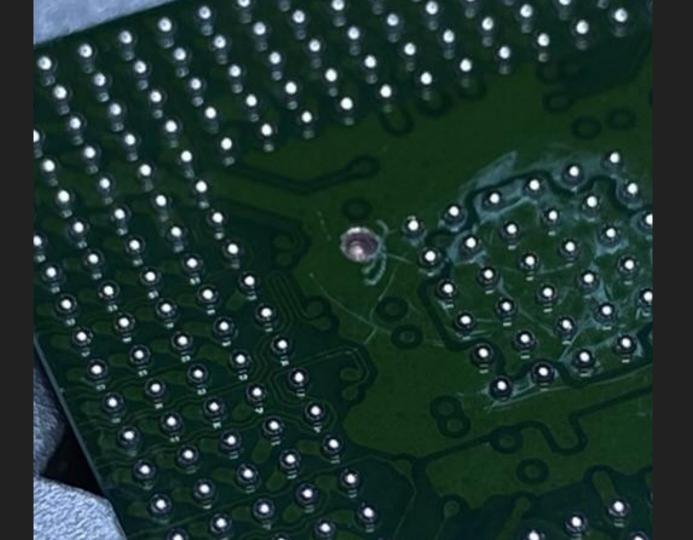


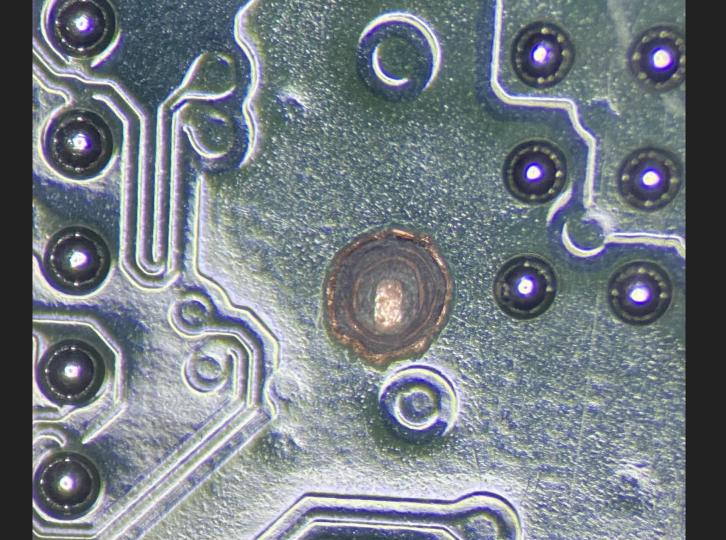


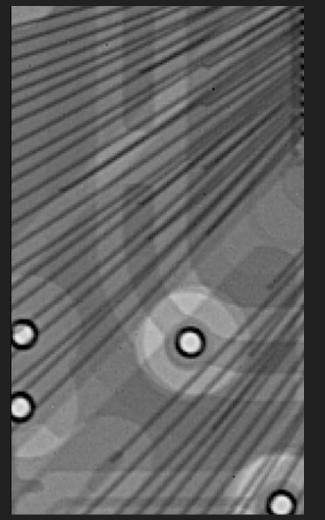
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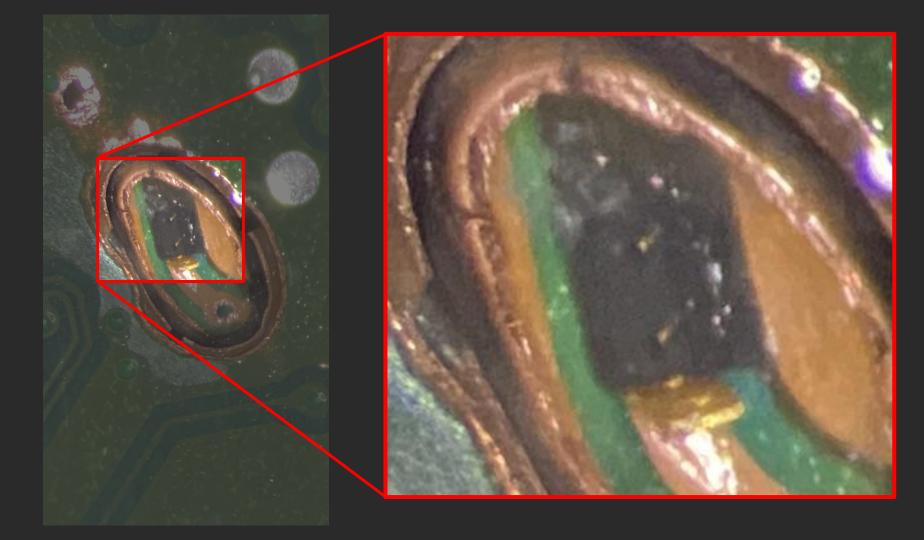
















my hair 80µm

> 42awg copper wire 64µm

> > gold bondwire 25µm

28awg dupont connector

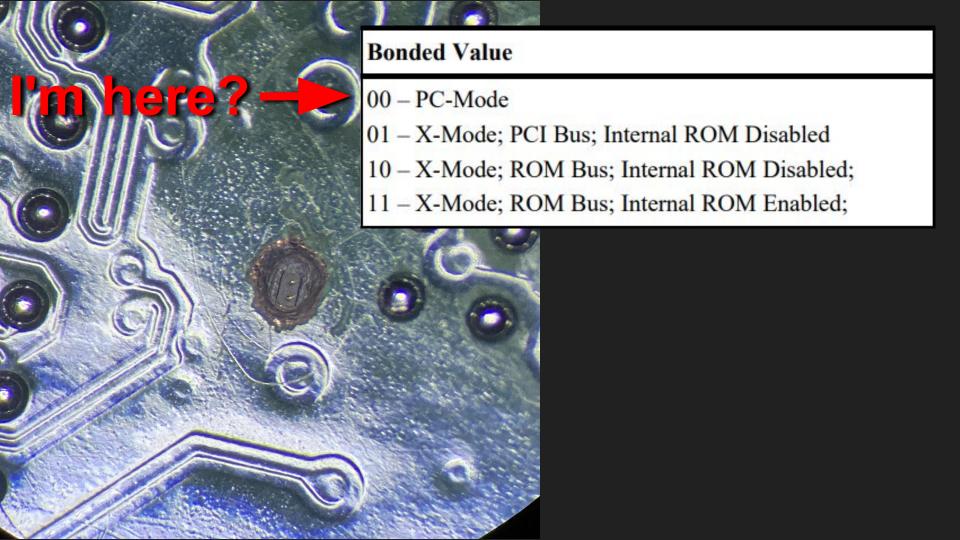


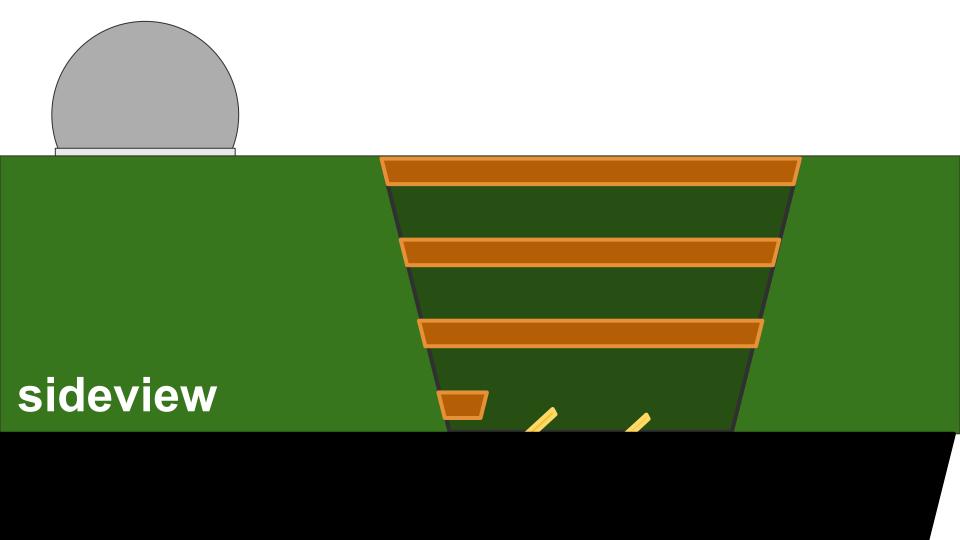
42awg copper wire 64µm

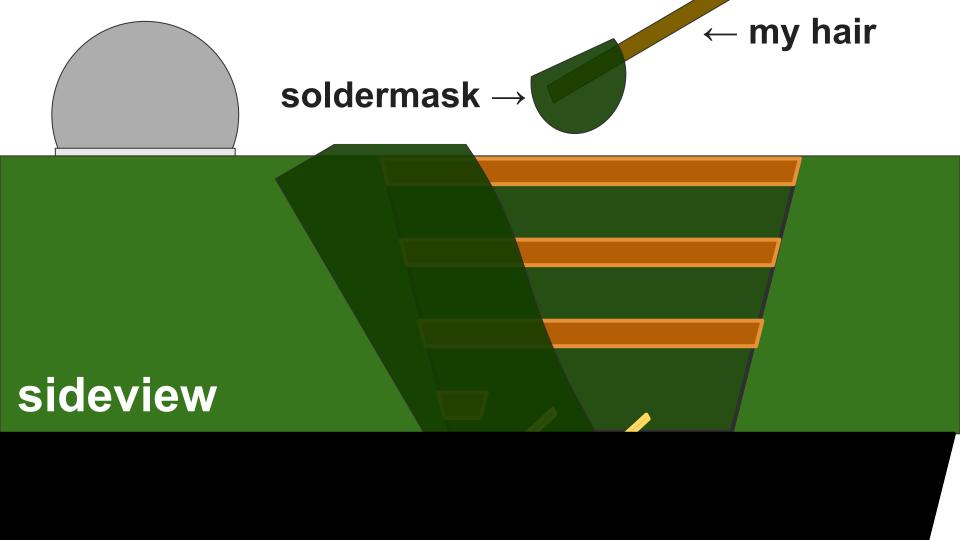
> gold bondwire 25µm

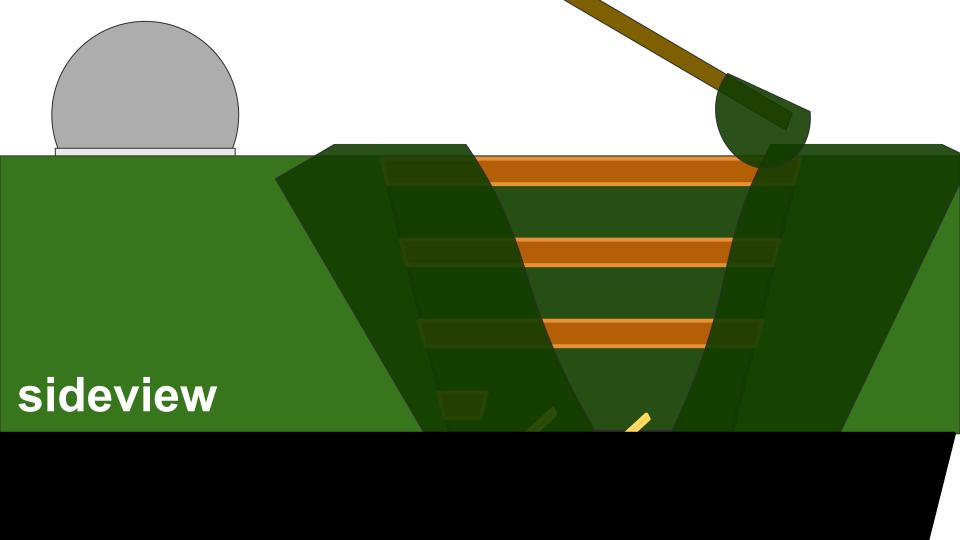
> > 1mm

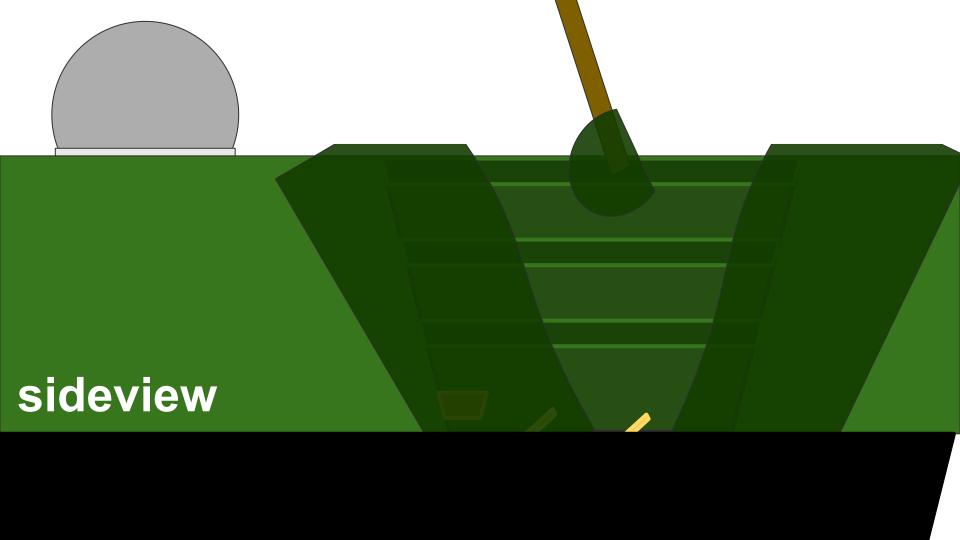
The Bodge

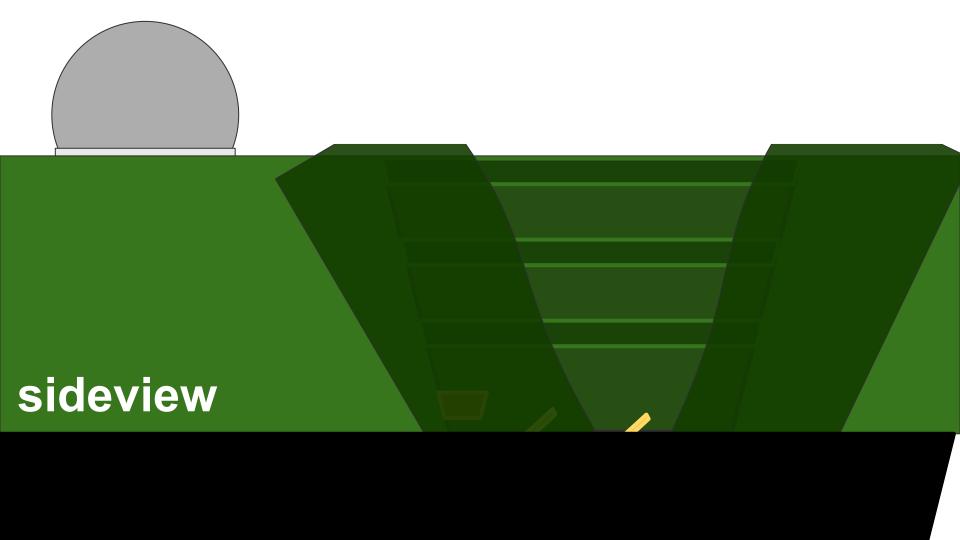


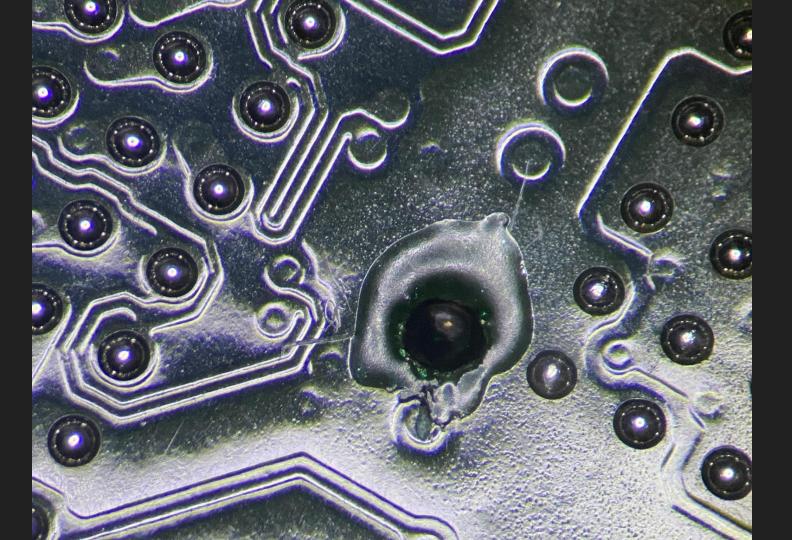


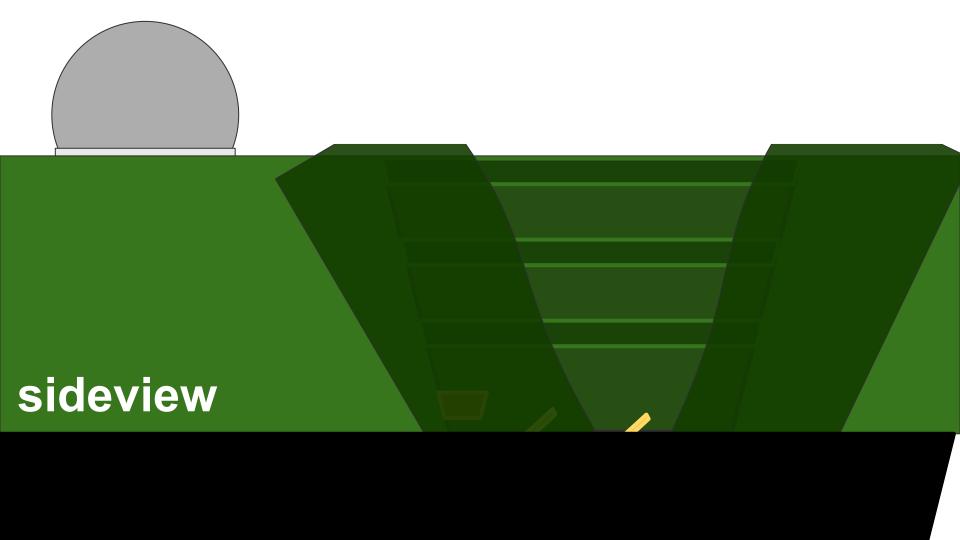


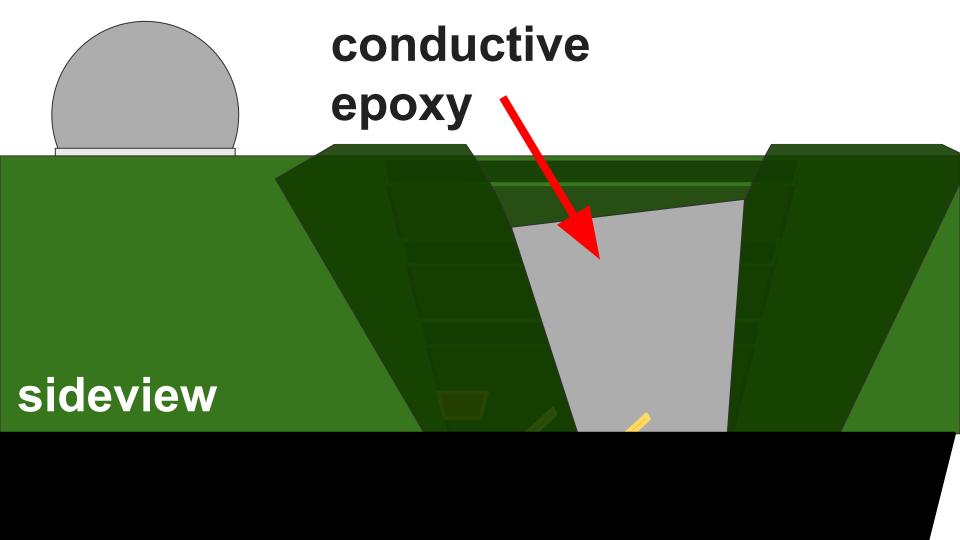


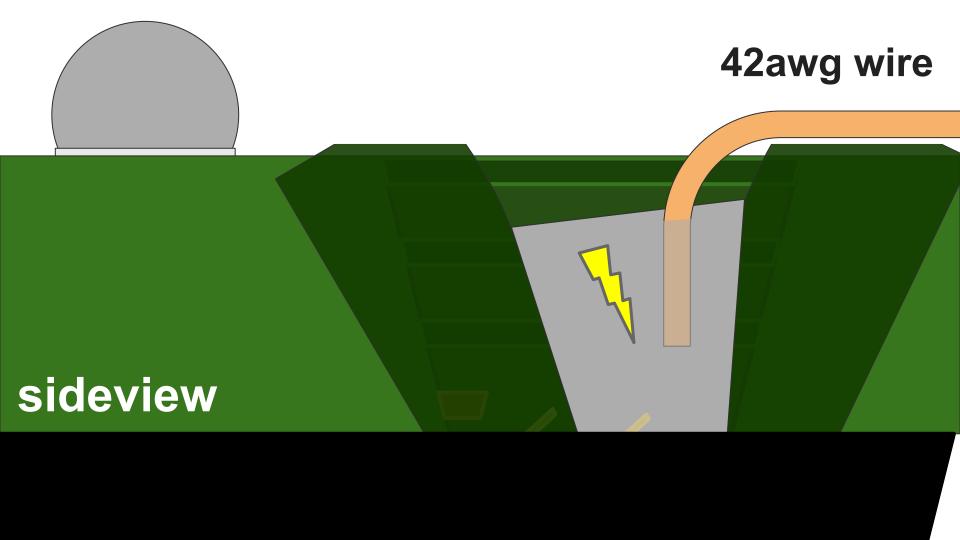


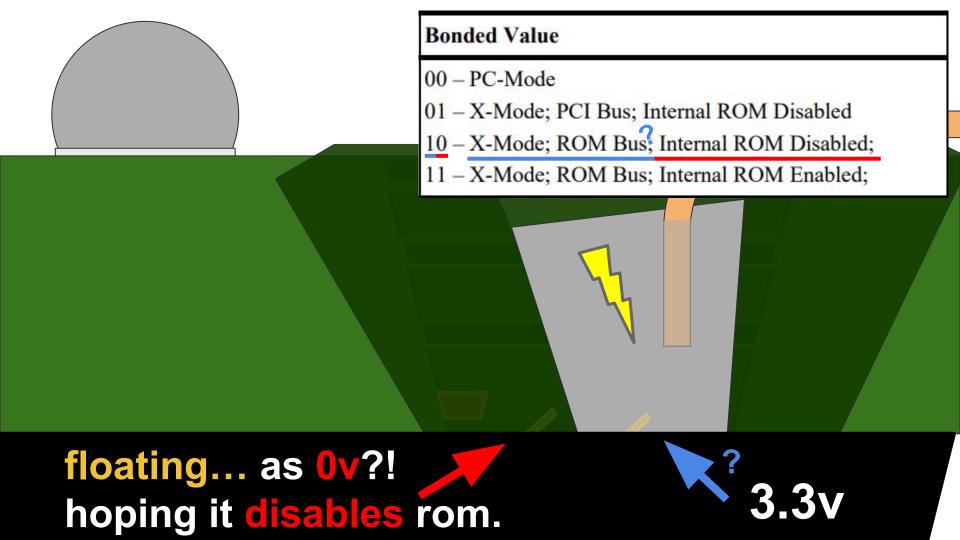


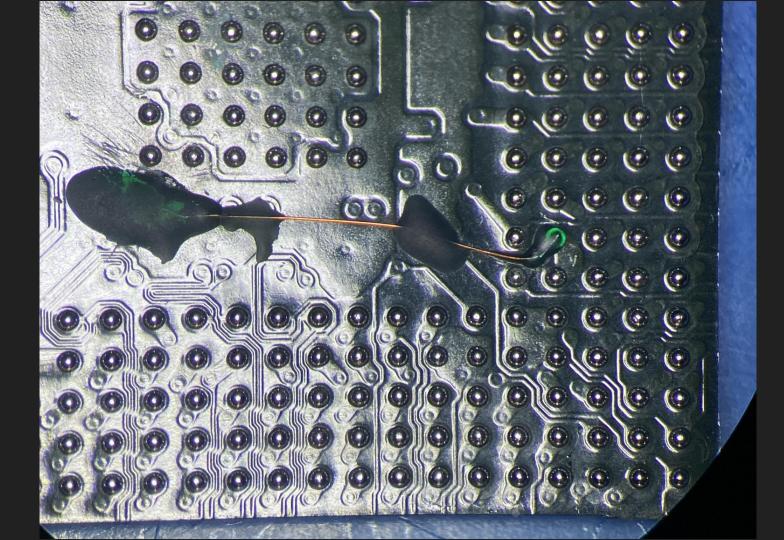


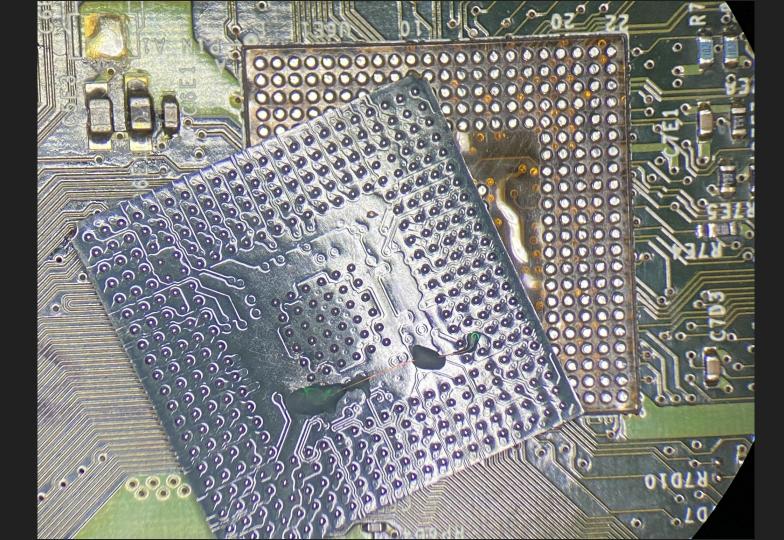


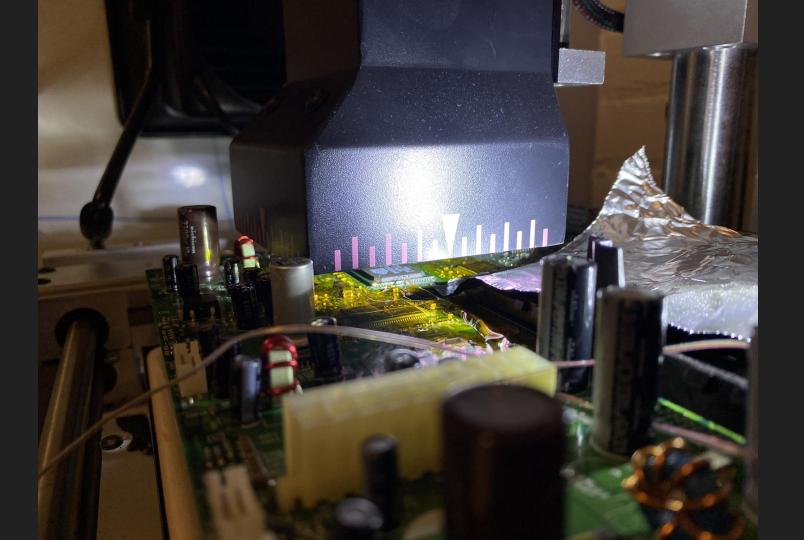














THE SYSTEM STILL BOOTS (1) (1)

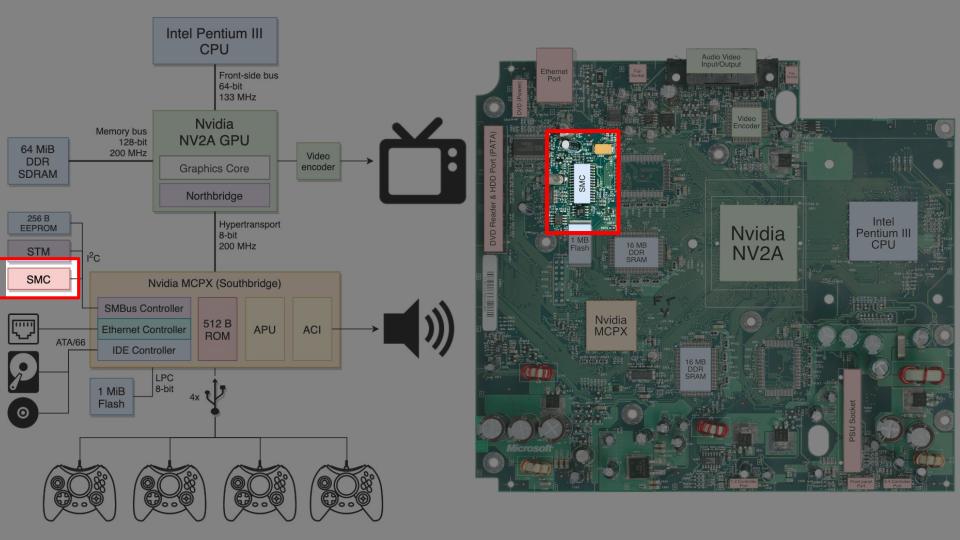


THE SYSTEM STILL BOOTS (1) (1)

... in retail mode.. 💢



System Management Controller



SMC - PIC16LC63A

System Management Controller

- Monitor power / eject button presses
- Monitor DVD tray state signals
- Drive fan PWM
- Front panel LED
- "SMC Challenge" / Boot security check

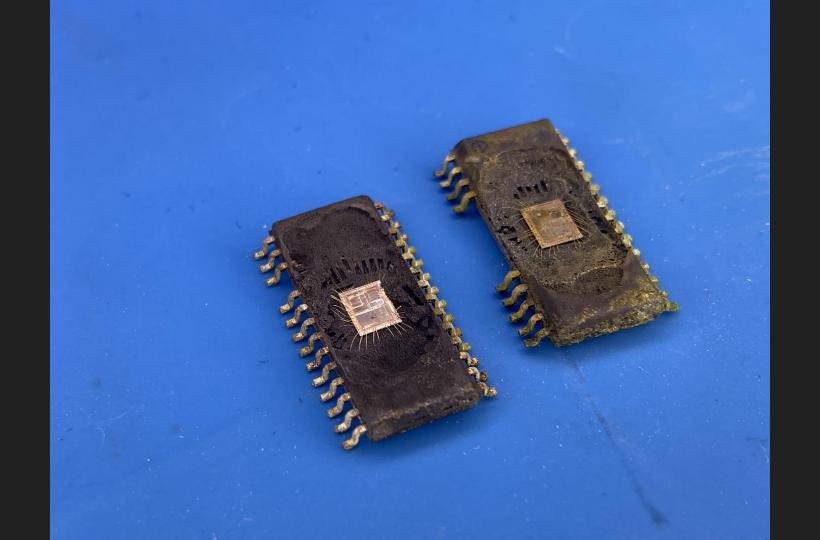
4KB of code - still undumped!

- Subtle differences between dev and retail SMC
- Good challenge to learn silicon RE!

Glitch, and UV-Erasure Resistant?

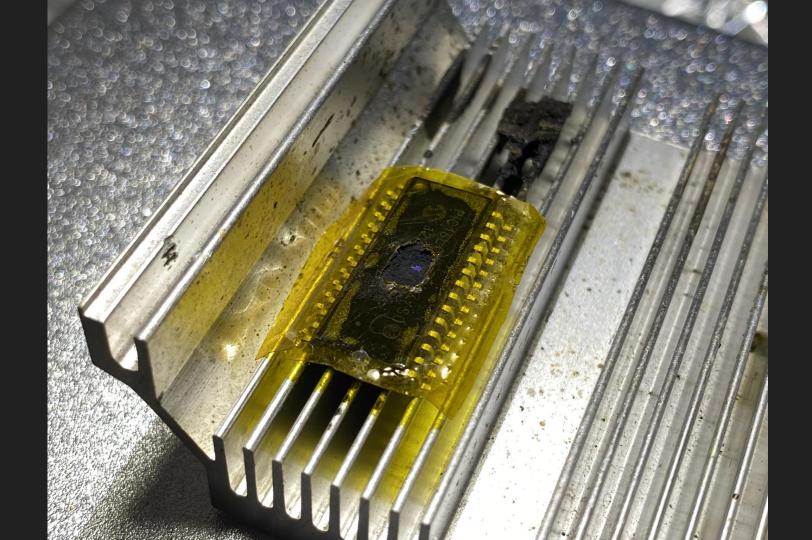
https://web.archive.org/web/20081222042941/http://www.flylogic.net/blog/?p=21



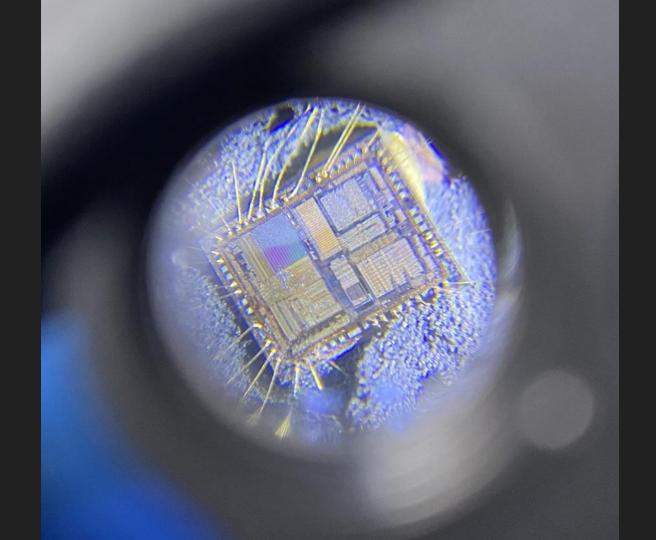


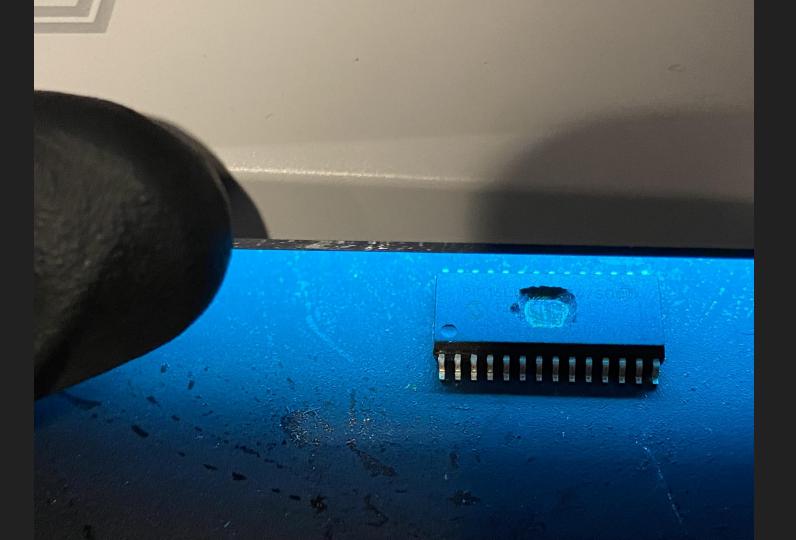


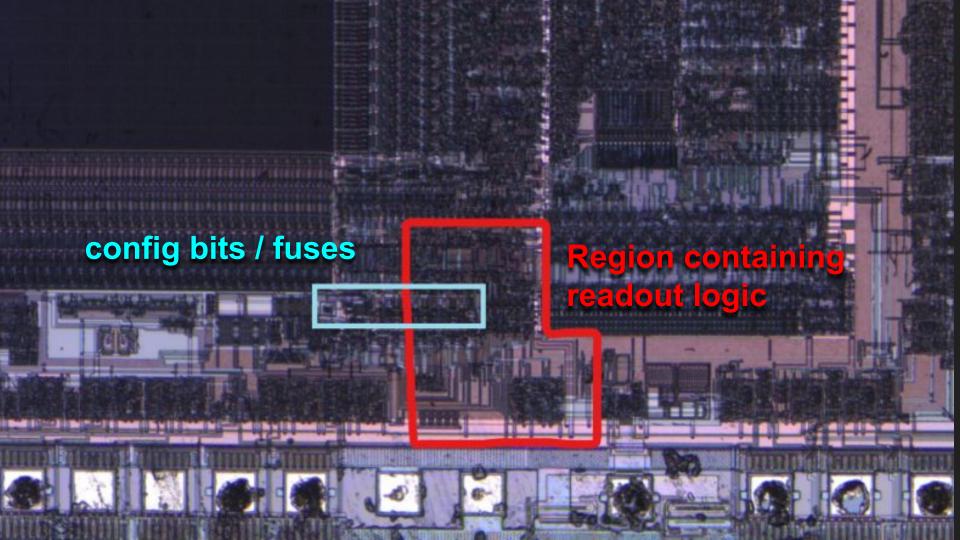


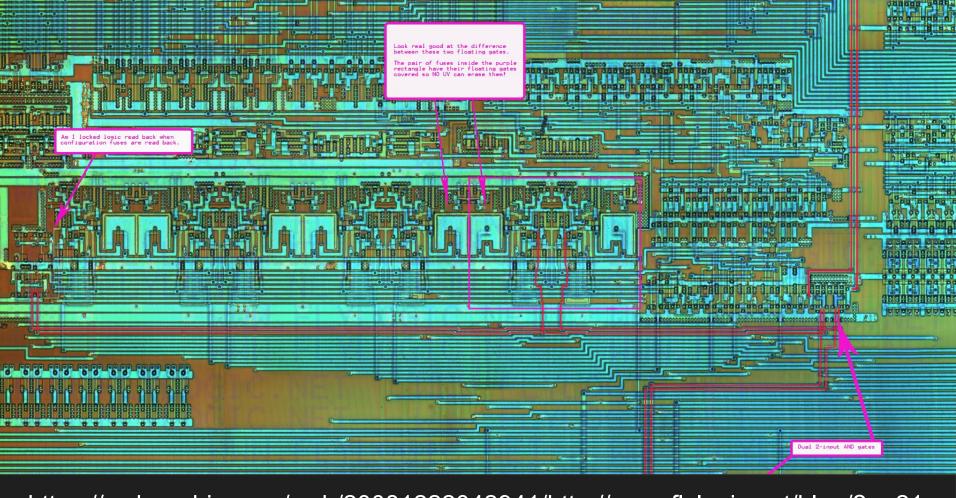












https://web.archive.org/web/20081222042941/http://www.flylogic.net/blog/?p=21



CPU Interposers



Xbox CPU

- Retail Xbox CPU 180nm Coppermine (SL5SN)
 - o 733mhz core
 - o 133mhz fsb
 - 128kb L2 cache
 - 1.7 volts
 - BGA2 / Micro-PGA2













10 Oct 2004 - 19 Dec 2021

13 captures

Categories

Xbox Skins

Articles

Gaming-Fever

New Articles (0)

All Articles (5)

Rebates (2)

DreamX (Gaming)

DreamX (Entertainment)

Xbox System Upgrades

Xbox Upgrade Peripherals

DreamX Comparison Charts (2)

Xbox Upgrades & Trade-In





DreamX-1480

Excellent as a High-End Media Center, Games Emulator, and for Linux on the Xbox

- (1) New Intel 1400MHz Celeron CPU
- (2) 1480/740MHz Switchable Speed
- (3) Memory Upgraded to 128MB
- (4) Pre-Modded (with Media Key installed)
- (5) 120GB Hard Drive + Media Center software
- (6) DreamX HDTV and A/V Cable included, for Component and S-Video Support
- (7) Dolby 5.1 and DTS 5.1 Surround Sound with Optical Fiber Audio Port
- (8) DVD Remote Control + USB Receiver
- (9) Xbox to USB Converter (for connecting an optional wireless keyboard & mouse)
- (10) Extra heatsink and heat conductive chain for improved heat dissipation
- (11) Rubber Pedestal Feet
- (12) New External Skin

200GB HDD Upgradability* No support for Xbox Live!** DVD movie playback requires XBMC***

Gaming-Fever (1) What's New?



USB Conversion Cable for Xbox \$4.95

Includes \$100 Trade-In Rebate Coupon



Features Comparison Chart



\$579.00

Click to enlarge

Shopping Cart

0 items

FAQ Categories

DreamX (13) Xbox System Upgrades (7) FriendTech MCE (2) Shipping (1) Support & Service (5)

Latest FAQs

What will a modehip upgrade allow me to How do I back up my games to the DreamX hard disk drive? Do you offer a 512MB memory upgrade for retail Xboxes?

Notifications 👸

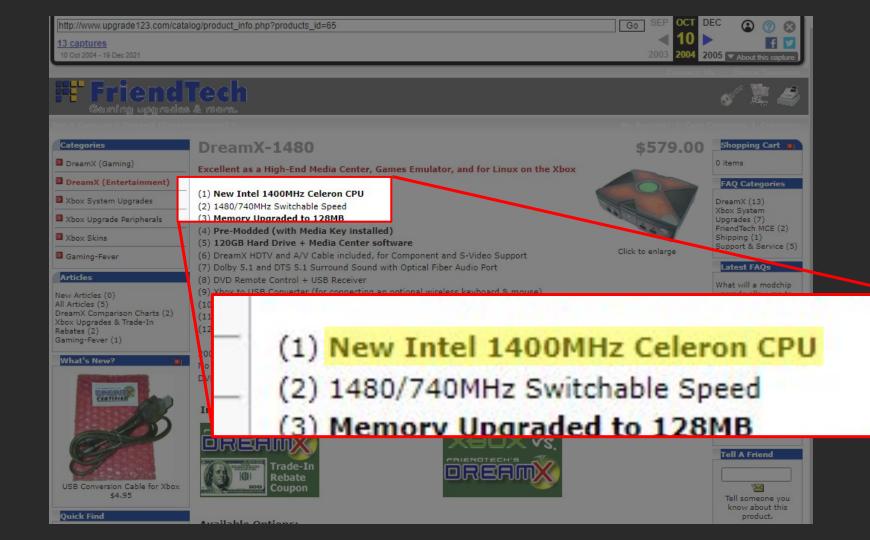


of updates DreamX-

Tell A Friend

Tell someone you know about this product.

Quick Find



Xbox CPU Comparison

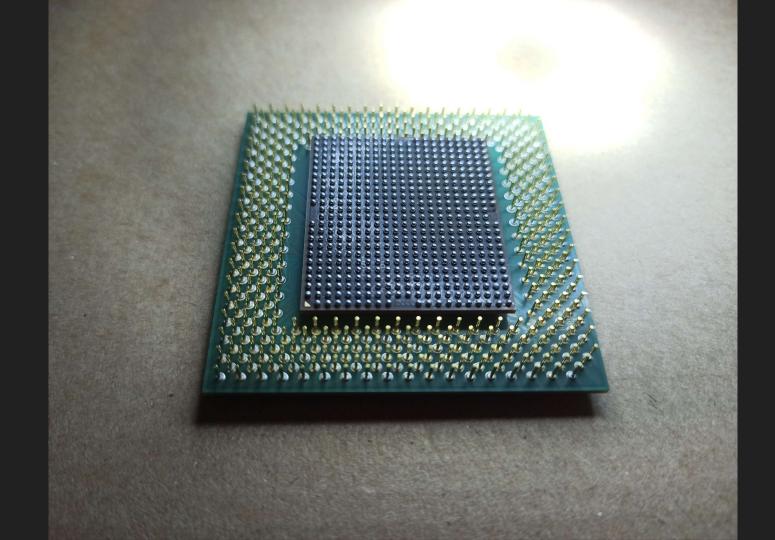
- Retail Xbox CPU 180nm Coppermine (SL5SN)
 - 733mhz core
 - o 133mhz fsb
 - 128kb L2 cache
 - 1.7 volts
 - BGA2 / Micro-PGA2
- Upgraded CPU 130nm Tualatin-S (SL6BY)
 - 1400mhz core (+90%)
 - 133mhz fsb
 - 512kb L2 cache (+300%)
 - 1.45 volts
 - Socket 370 / PGA370

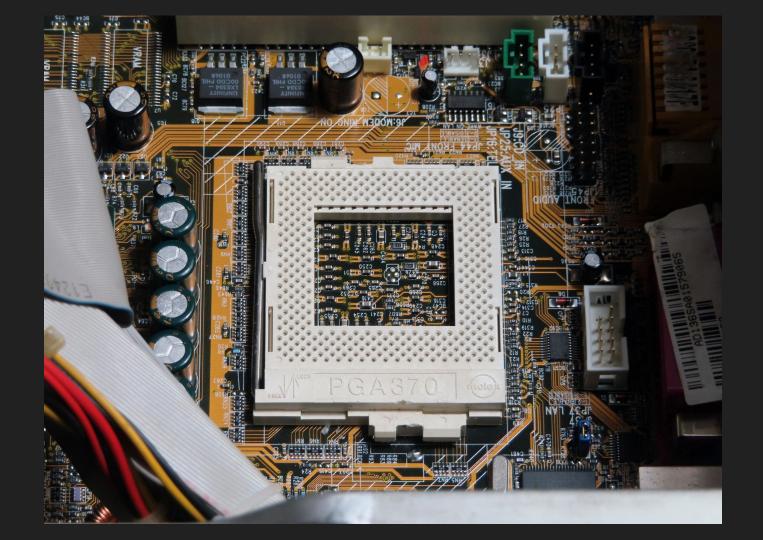
Xbox CPU Comparison

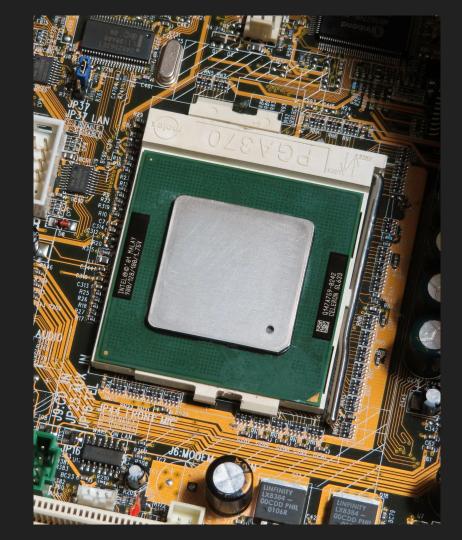
- Retail Xbox CPU 180nm Coppermine (SL5SN)
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 - 1400mhz core (+90%)
 - 133mhz fsb
 - 512kb L2 cache (+300%)
 - 1.45 volts
 - Socket 370 / PGA370











BGA2 → PGA370 CPU Interposer



US 20050282621A1

(19) United States

(12) Patent Application Publication (10) Pub. No.: US 2005/0282621 A1 Hu

Dec. 22, 2005 (43) Pub. Date:

- CPU UPGRADING ADAPTER FOR A MICROSOFT XBOXTM GAME MACHINE
- Inventor: Ta-Shin Hu, Sanchung City (TW)

Correspondence Address: NIKOLAI & MERSEREAU, P.A. 900 SECOND AVENUE SOUTH **SUITE 820** MINNEAPOLIS, MN 55402 (US)

- (21) Appl. No.: 10/645,383
- (22)Filed: Aug. 21, 2003

Publication Classification

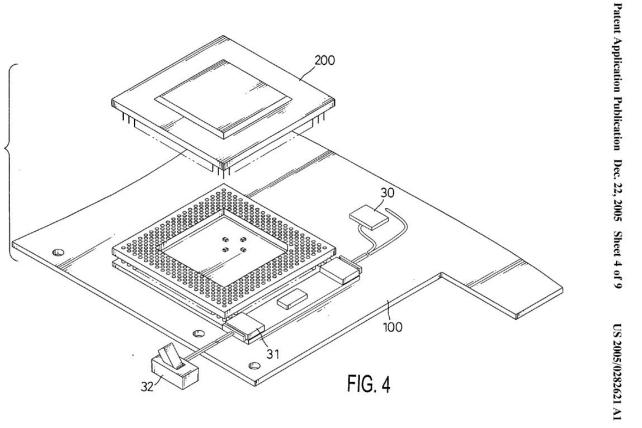
- (57)ABSTRACT

A CPU upgrading adapter for an XBOX game machine is composed of a circuit board on which a socket frame and a switched are electrically connected. When the original CPU is removed from a motherboard of the XBOX game machine, the CPU upgrading adapter is then mounted on the motherboard to receive a new high speed upgrading CPU. Such an upgrading CPU is chosen from an Intel® Pentium-III-S™ CPU, a Pentium-III™ CPU or a Celeron™ CPU.

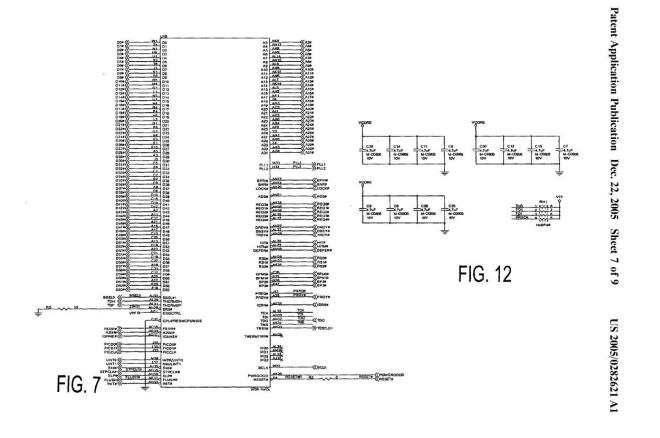
External Power

+3.3V

"CPU upgrading adapter for a Microsoft XboxTM game machine, Patent # US 2005 / 0282621 A1"

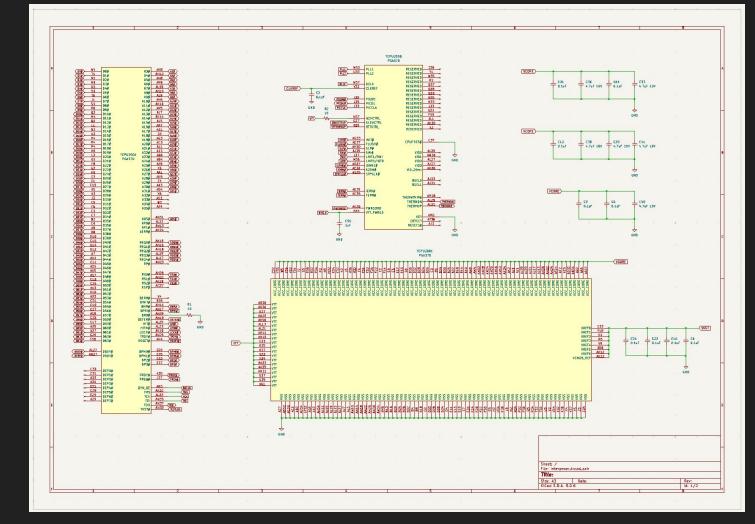


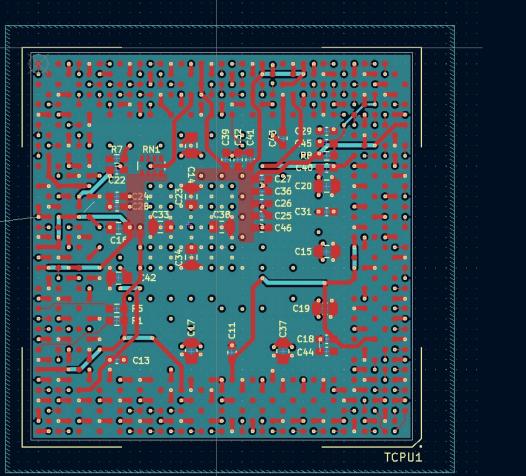
"CPU upgrading adapter for a Microsoft XboxTM game machine, Patent # US 2005 / 0282621 A1" (Page 4)



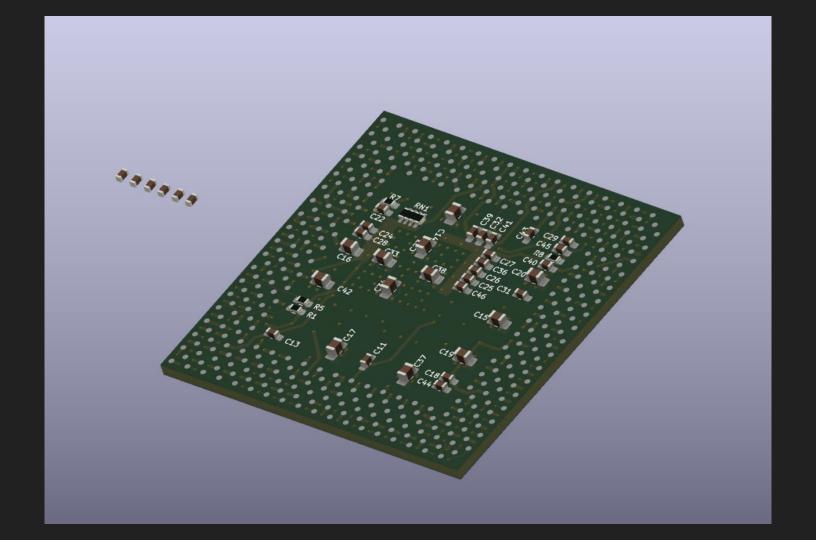
"CPU upgrading adapter for a Microsoft XboxTM game machine, Patent # US 2005 / 0282621 A1" (Page 7)

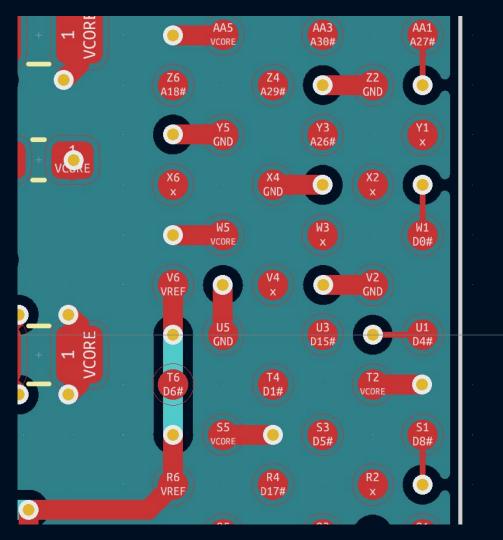






C35 C21





performance against actual system measurements.

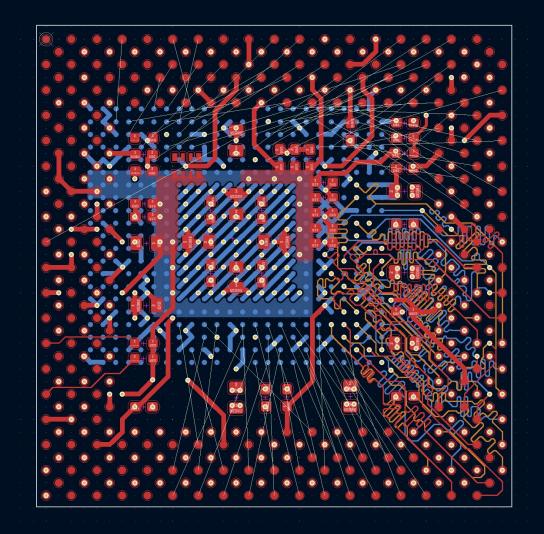
Intel® Pentium® III Processor with 512KB L2 Cache DP I/O buffer models are available from the Intel Developer website.

3.6 Trace Routing

The following guidelines should be followed when routing the AGTL host bus signal traces:

- Traces should have an impedance of 60Ω +/- 15%
- · The nominal trace width should be 5 mils.
- The L0 and L1 lengths in Table 3-5 should be matched to within 0.25 inches.
- · Minimize the number of vias and layer transitions.

3.7 Layout Rules for AGTL Signals



performance against actual system measurements.

Intel[®] Pentium[®] III Processor with 512KB L2 Cache DP I/O buffer models are available from the Intel Developer website.

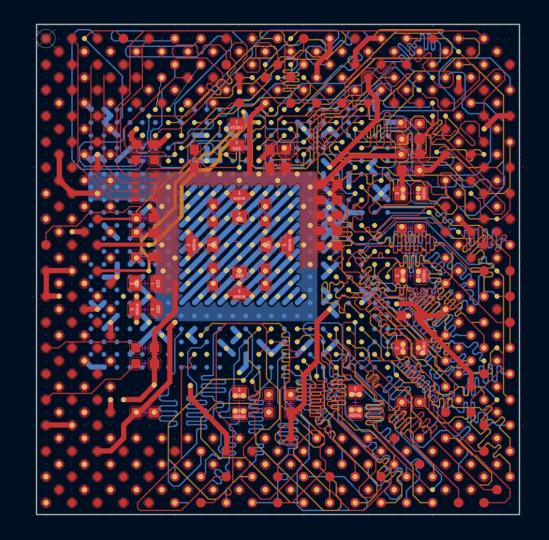
3.6 Trace Routing

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• Traces should have an impedance of 60Ω +/- 15%

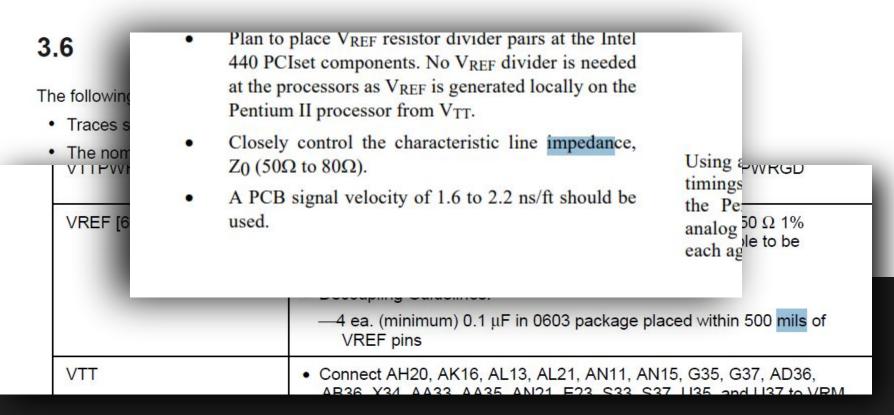
· The nominal trace width should be 5 mils.

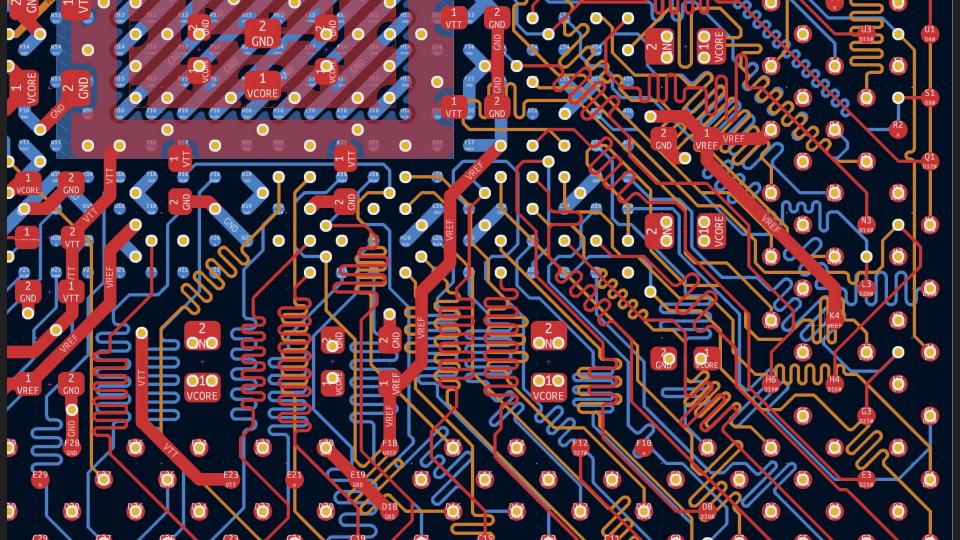
VIIPWKGD	Pull-up to VII through T K12 resistor and connect to VIIPWKGD circuitry. See Section 4.2.6.
VREF [6:0]	• Connect to VREF voltage divider made up of 75 Ω and 150 Ω 1% resistors connected to VTT. Processor VREF must be able to be separate from chipset VREF.
	Decoupling Guidelines:
	—4 ea. (minimum) 0.1 μF in 0603 package placed within 500 mils of VREF pins
VTT	Connect AH20, AK16, AL13, AL21, AN11, AN15, G35, G37, AD36, AB36, V34, AA33, AA35, AN21, E23, S33, S37, U35, and U37 to VRM



performance against actual system measurements.

Intel[®] Pentium[®] III Processor with 512KB L2 Cache DP I/O buffer models are available from the Intel Developer website.





performance against act

Intel[®] Pentium[®] III Proce Developer website.

3.6

The following

- Traces s
- The non

VREF [6

VTT

AP-585

intel

package, shared by 13 to 19 resistors (for 14- and 20-pin components). These packages generally have too much inductance to maintain the voltage/current needed at each resistive load. Intel recommends using discrete resistors, resistor networks that have separate power/ground pins for each resistor, or working with a resistor network vendor to obtain resistor networks that have acceptable characteristics.

5.0. MORE DETAILS AND INSIGHTS

5.1. Textbook Timing Equations

The textbook equations used to calculate the propagation rate of a signal in a PCB are the basis for spreadsheet calculations for timing margin. These equations are:

Equation 7. Intrinsic Impedance

$$Z_0 = \sqrt{\frac{L_0}{C_0}}$$

Equation 8. Stripline Intrinsic Propagation Speed

$$S_{0}$$
 STRIPLINE = 1.017 * $\sqrt{\varepsilon_r}$

Equation 9. Microstrip Intrinsic Propagation Speed

$$S_0$$
 MICROSTRIP = $1.017 * \sqrt{0.475 * \varepsilon_r + 0.67}$

Equation 10. Effective Propagation Speed

$$S_{EFF} = S_0 * \sqrt{1 + \frac{C_D}{C_0}}$$

Equation 11. Effective Impedance

Equation 12. Distributed Trace Capacitance

$$C_0 = \frac{S_0}{Z_0}$$

Equation 13. Distributed Trace Inductance

$$L_0 = Z_0 * S_0$$

Where (for Equation 7 through Equation 13):

S₀ = The speed of the signal on an unloaded PCB. This is referred to as the board propagation constant.

So MICROSTRIP and So STRIPLINE

- The speed of the signal on an unloaded microstrip or stripline trace on the PCB.
- Z0 = The intrinsic impedance of the line and is a function of the dielectric constant (ε_t), the line width, line height and line space from the plane(s). The equations for Z₀ are not included in this document. See the MECL. System Design Handbook by William R. Blood, Jr. for these equations.
- C₀ = The distributed trace capacitance per unit length of the network.
- E₀ = The distributed trace inductance per unit length of the network.
- C_D = The sum of the capacitance of all devices and stubs divided by the length of the network's trunk, not including the portion connecting the end agents to the termination resistors.

SEFF and ZEFF

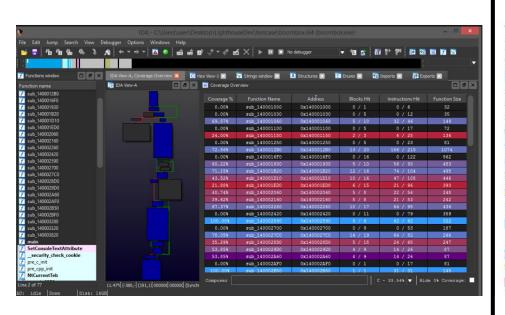
The effective propagation constant and impedance of the PCB when the board is "loaded" with the components. e from the Intel

Using a VVKGD timings the Peranalog 50 Ω 1% each ag

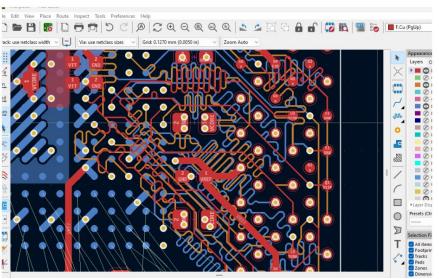
ed within 500 mils of

5, G35, G37, AD36,

how it started



how it's going

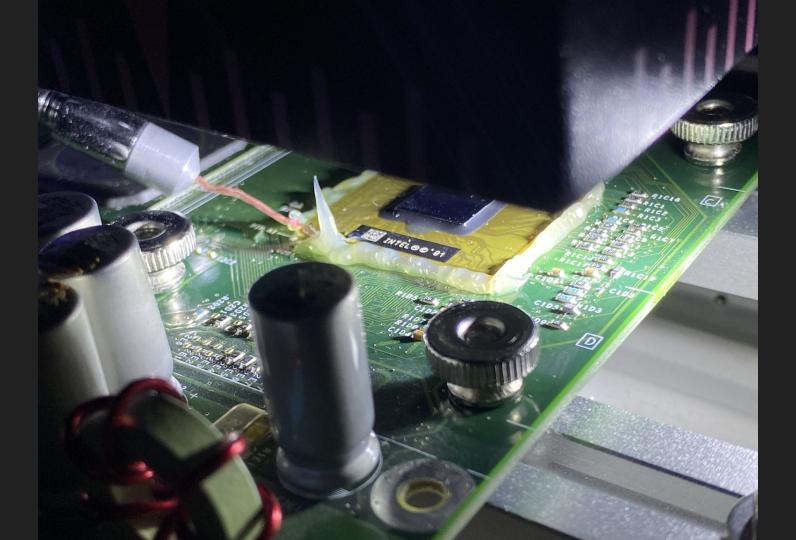




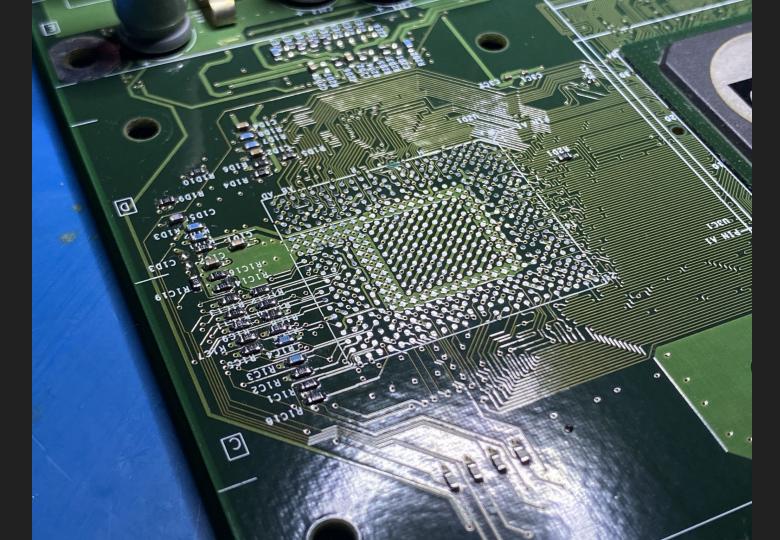
The Install

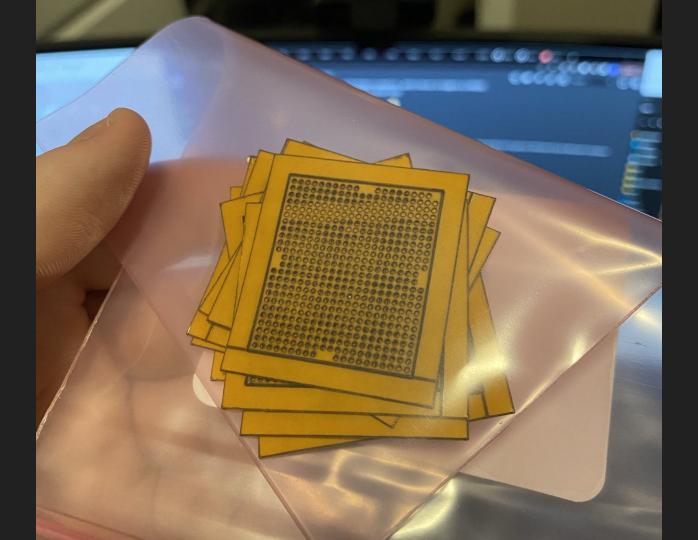


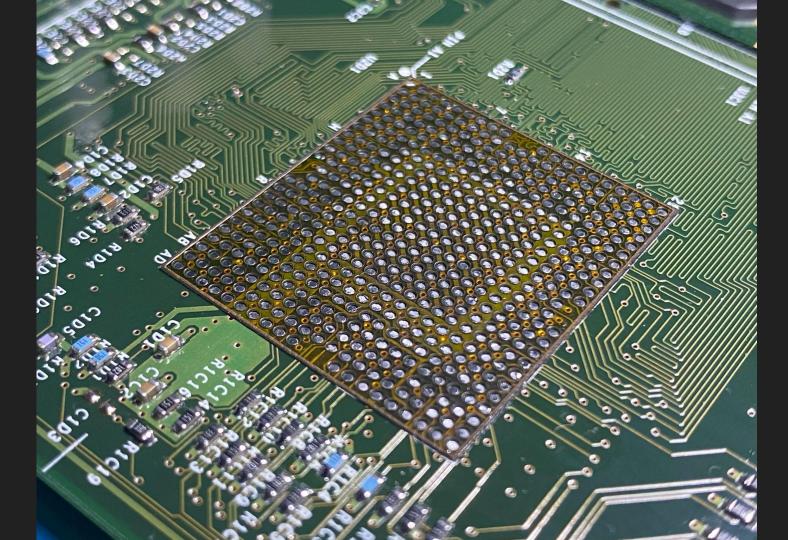




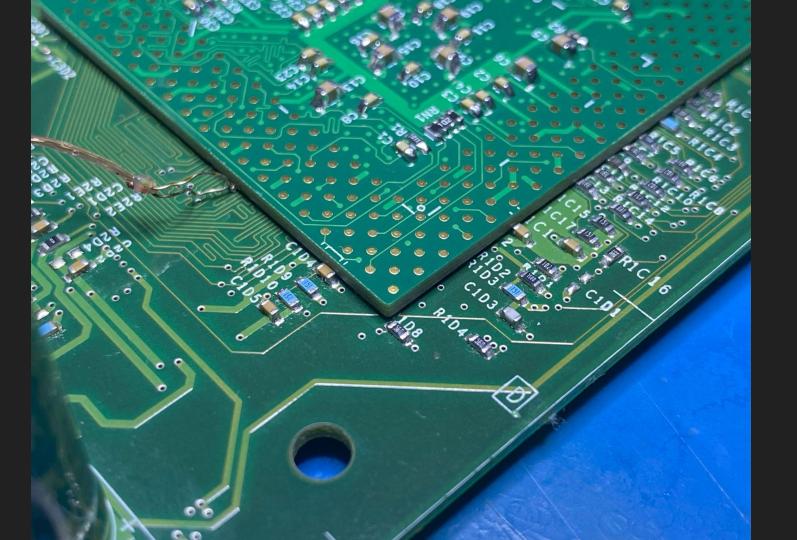




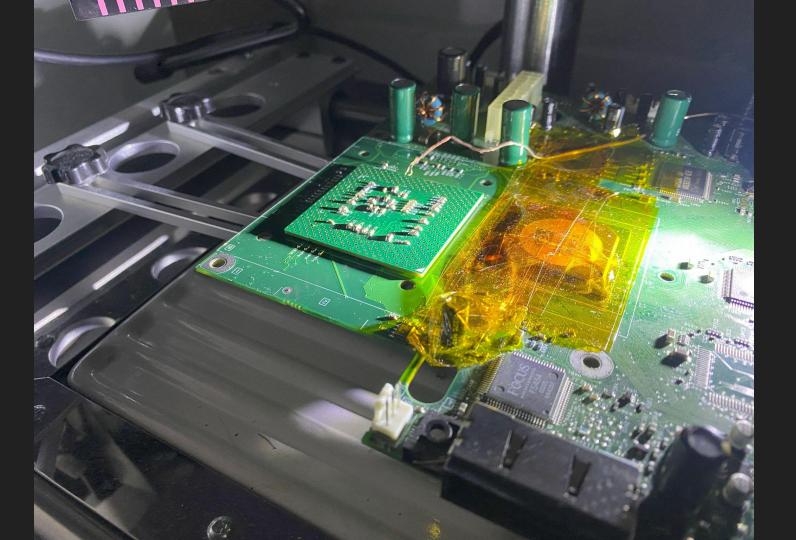


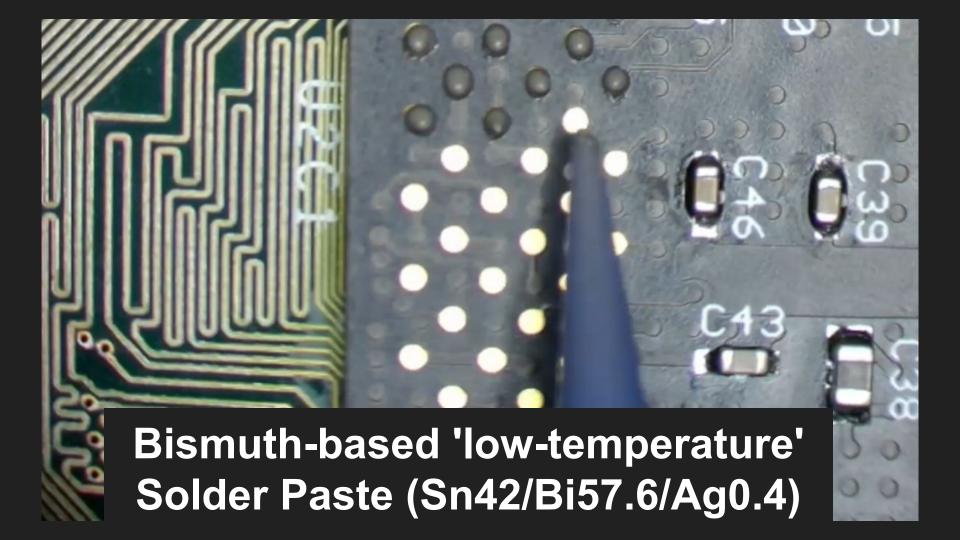


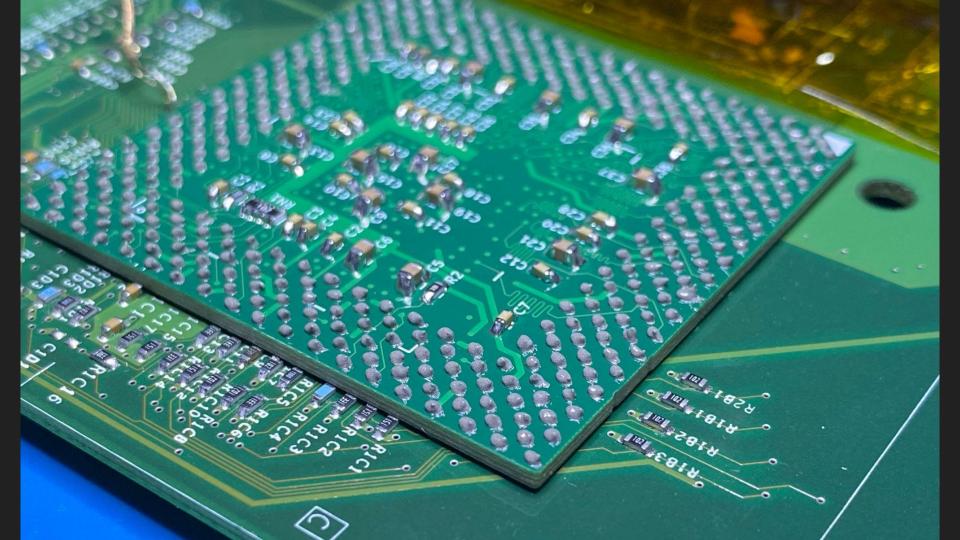






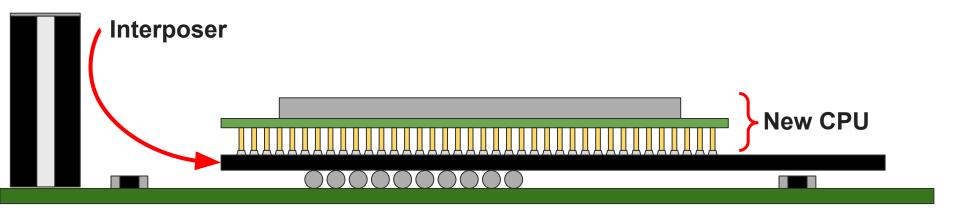






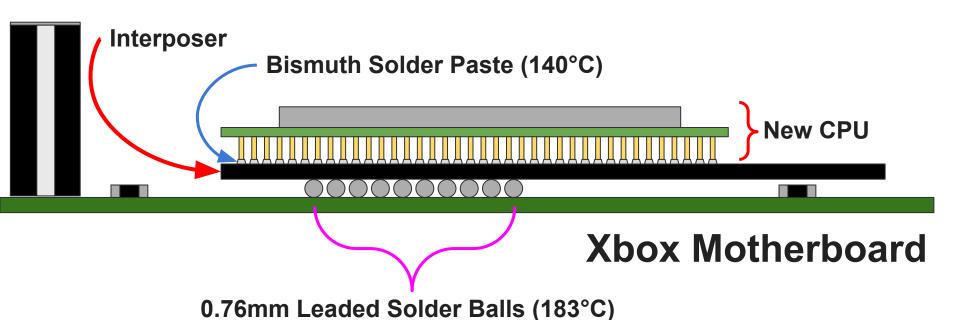


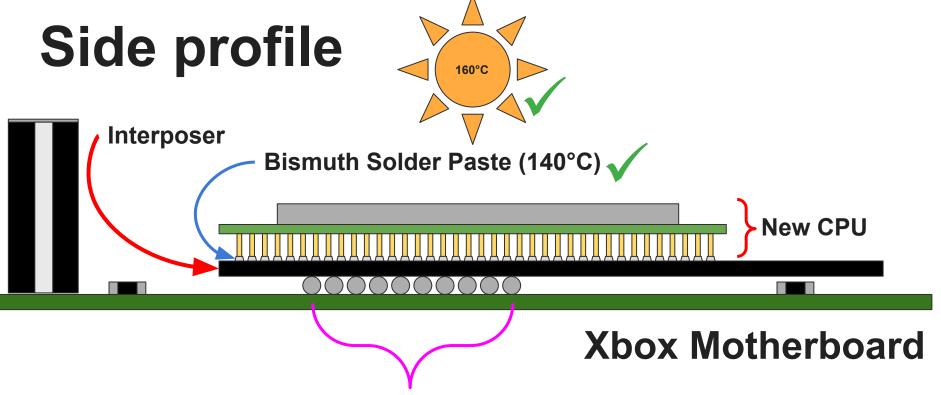
Side profile



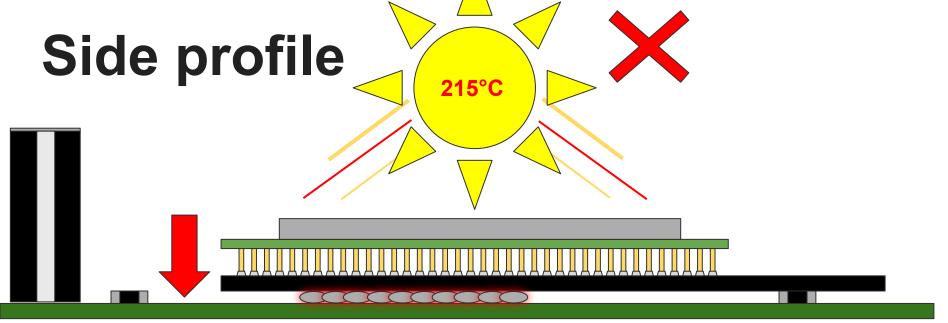
Xbox Motherboard

Side profile





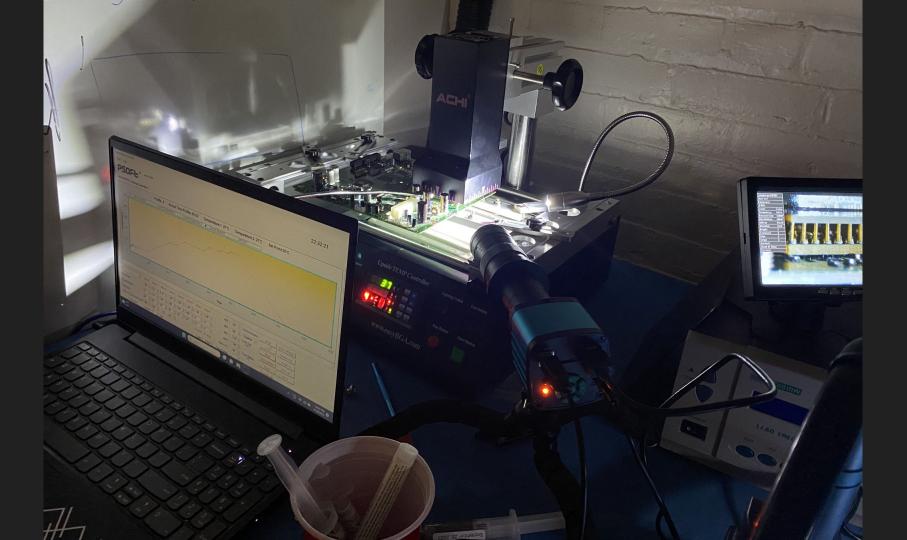
0.76mm Leaded Solder Balls (183°C)

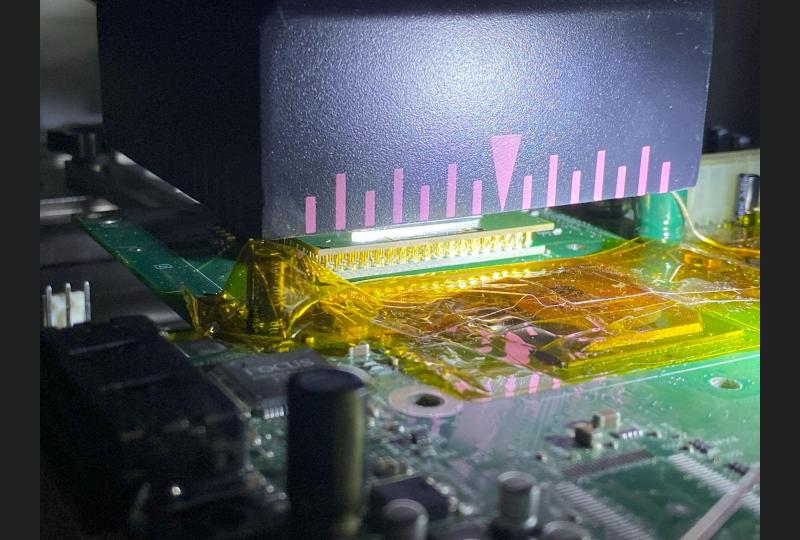


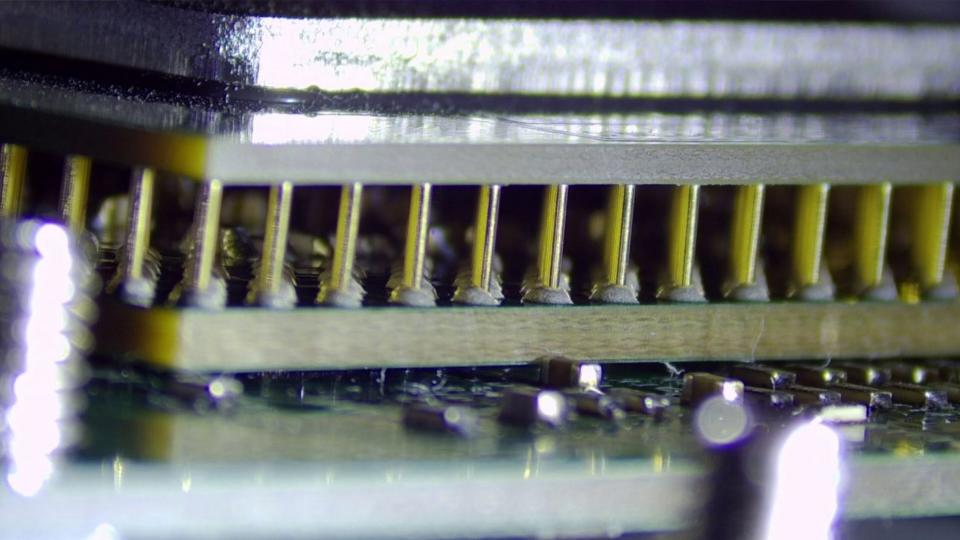


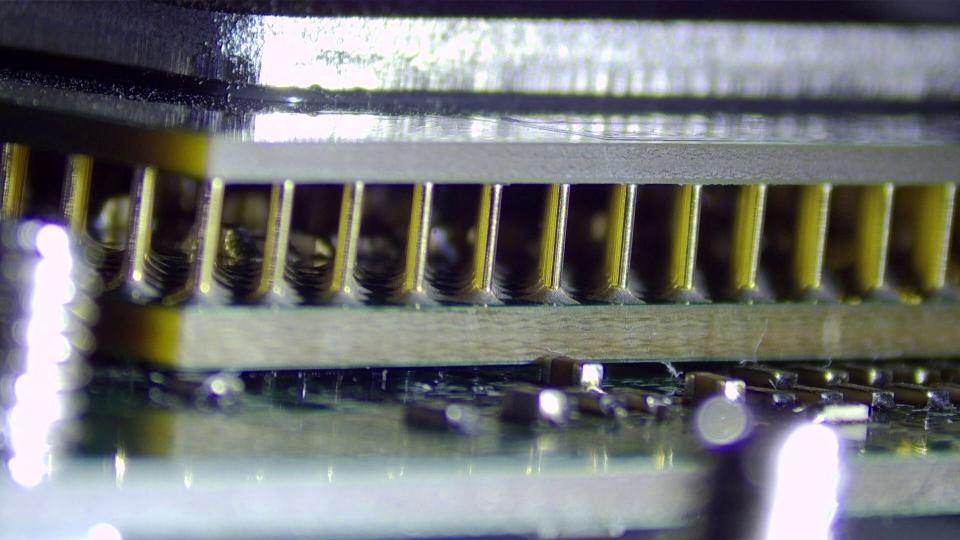
Xbox Motherboard

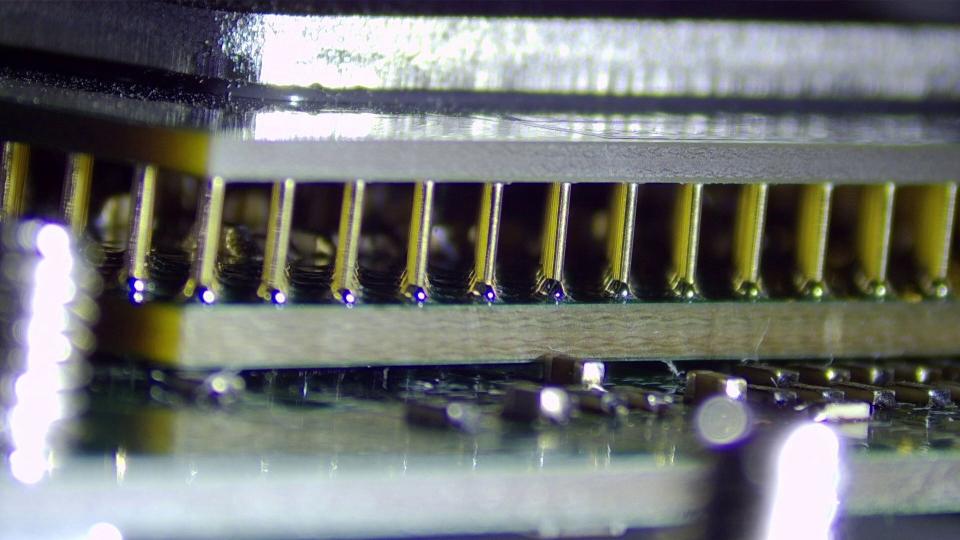
bridging BGA balls under interposer









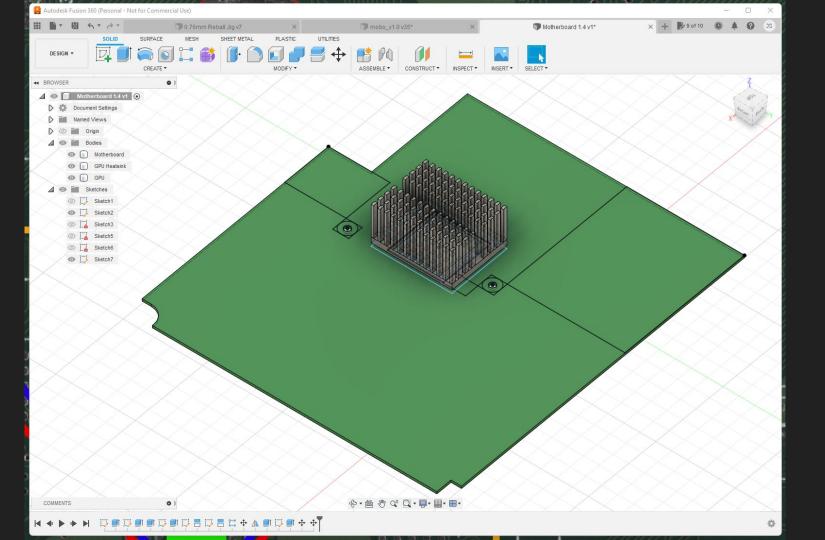


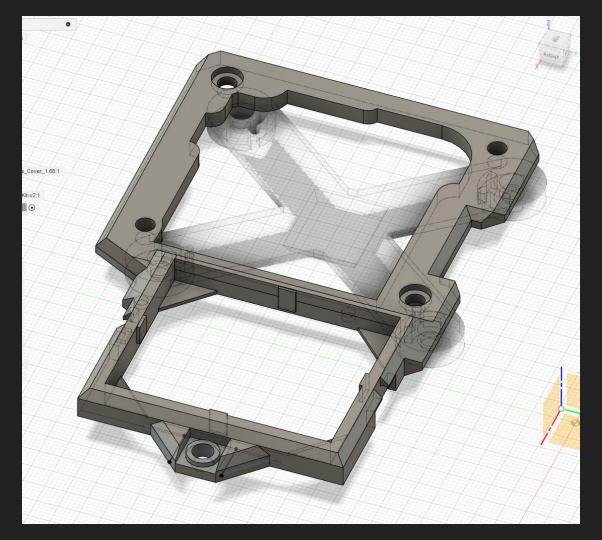






wait... how do l cool this thing?



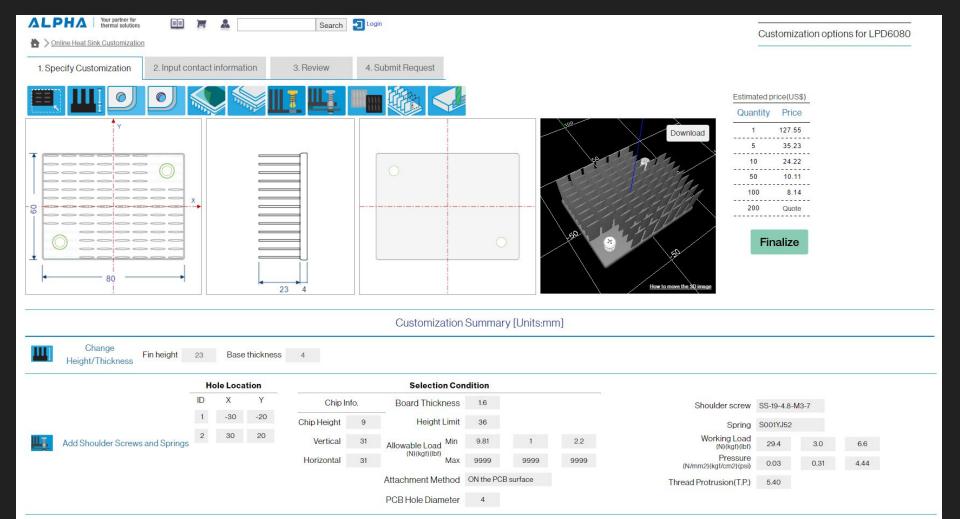


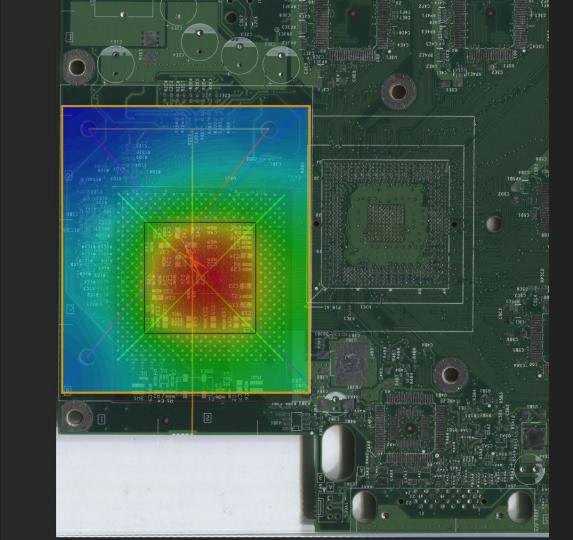


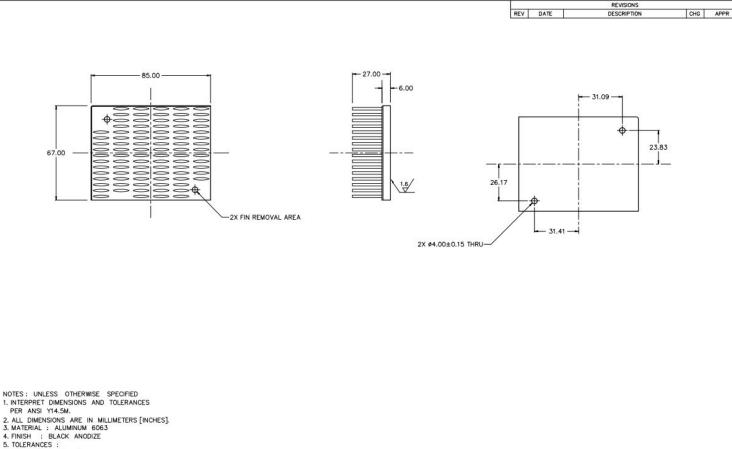








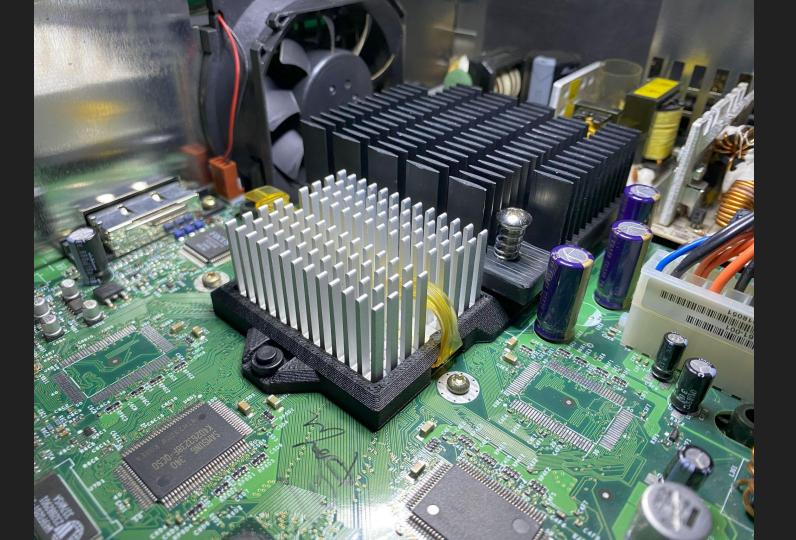


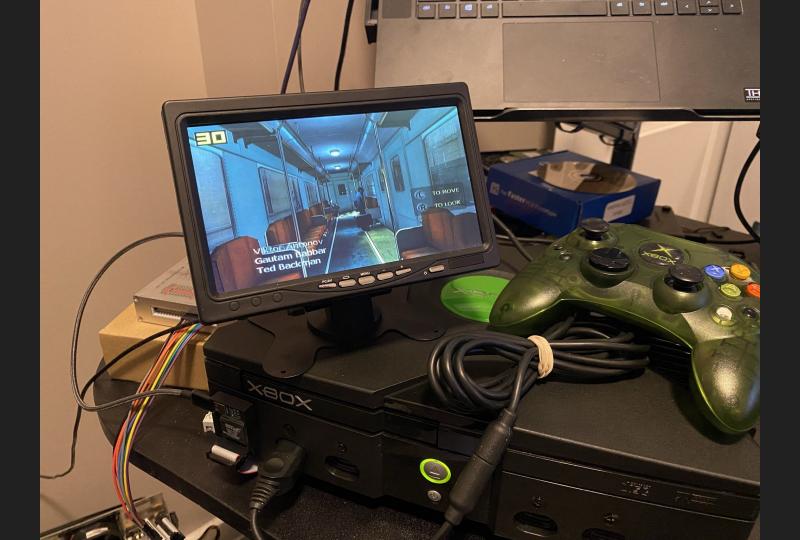


.XX ±0.254 [.010]
.XXX ±0.127 [.005]
ANGLES ± 1°
REMOVE ALL BURRS AND BREAK SHARP EDGES.
UNSPECIFIED CORNER RO.5 MAX OR CO.5 MAX.
7. A BEND OF THE FIN: THE FINS MUST NOT CONTACT.
8. FIN REMOVAL MARKS MAX 0.3MM
9. BASED ON ALPHA STANDARD HEAT SINK W100-45W

REMARK Q*	PART NAME	PART NO.	ITEM
CSTMR'S PART NO.	COLTD.	ALPHA	
W6785-27BM-RA8	MATERIAL NOTE 3,4		<u>Ф</u> -
PART NO. & DWG NO. RE	APPR & CHCK G.SUMMERFIELD	CALE : 1	
	DSGN & DWG	ATE	
DCTN: LOFF:	G.SUMMERFIELD	9, 2023	JAN 1









Half Life 2



























https://blog.ret2.io/2023/08/09/jtag-hacking-the-original-xbox-2023/

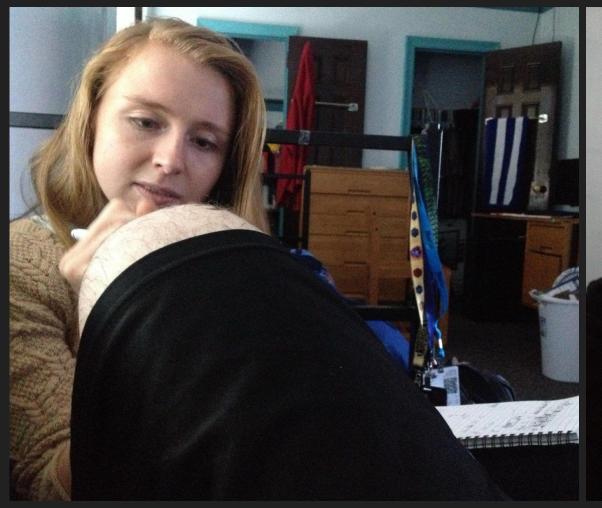


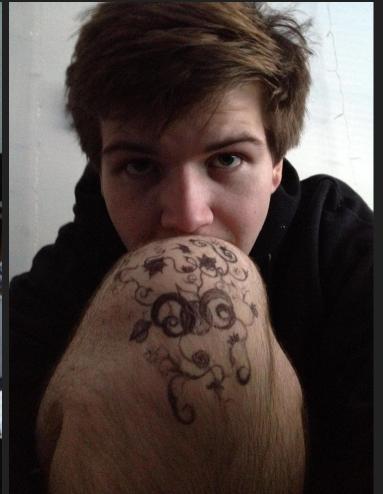
bunnie 7/14/23, 3:33 AM oh wow. the PCB interposer is genius.

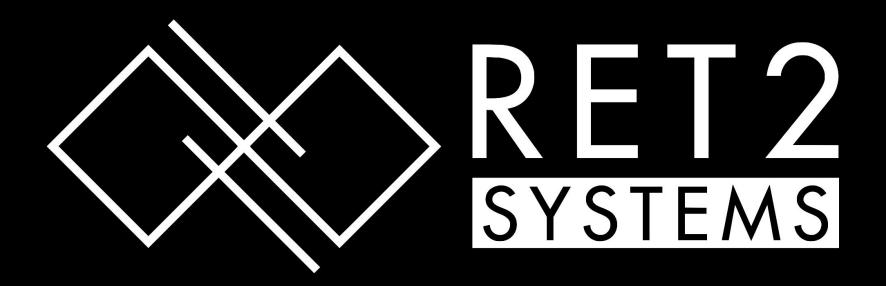


Epilogue











MARGIN

RESEARCH





Sophia "quend" d'Antoine was an amazing woman, researcher, and friend. She sat at the heart of the RPISEC family and was an important part of our story.

Her individual grace and ambition was felt across the industry. She inspired and touched so many lives.

Sophia's vision and passion will continue to be the cornerstone of our collective aspirations.

1993 - 2024









Conclusions

Be ambitious, ignorance is bliss

Hug your friends

Special acknowledgements

 grimdoomer, xbox7887, 404, dustin, x, loser, mborgerson, libby, ryzee119, andy, disco, Insignia folks, haxar, prehistoricman, frank, archive.org, fish





doom@aol.com

DO YOU HAVE THIS **BOARD?**

(A1 / EVT)

\$5000 USD Bounty

